Service Manual

Telephone Equipment
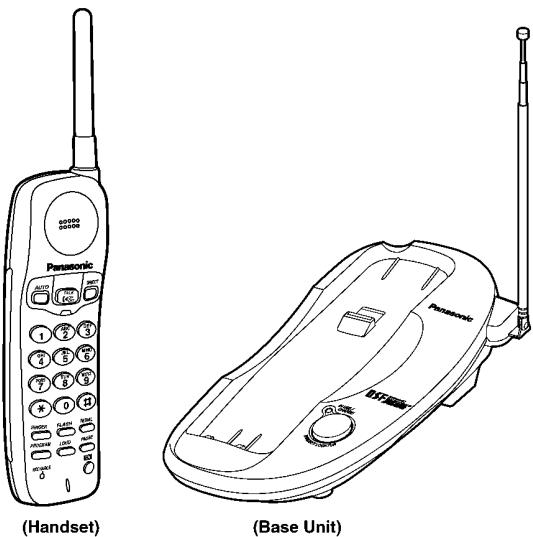
KX-TC2000NZB
KX-TC2000NZW
KX-TC2000NZF

Cordless Phone

Black Version

White Version

Blue Version

(for New Zealand)

(Handset)   (Base Unit)

SPECIFICATIONS

General

Modulation:	FM, 5kHz Deviation
Frequency Stability:	± 2.5 kHz
Dial Type:	Tone (DTMF)
Redial:	Last dialed number each time the Redial button is pressed

Pause:	3.5 seconds per pause
Memory Capacity:	10 telephone numbers, up to 16 digits per station

	Base Unit	Handset
Power Source:	AC adaptor PQLV16ALZ (DC 12 V)	Built-in rechargeable Ni-Cd battery
(Receiver Section)		
Receiving Frequency:	10 channels within 39.775 to 40.000 MHz	10 channels within 30.075 to 30.300 MHz
Adjacent Channel Rejection:	40 dB	40 dB
Sensitivity:	1dBµV for 20 dB S/N	2 dBµV for 20 dB S/N
(Transmitter Section)		
Transmitting Frequency:	10 channels within 30.075 to 30.300 MHz	10 channels within 39.775 to 40.000 MHz
Jacks:	DC IN, Telephone line	
Antenna:	Telescopic	Rubber Flexible
Speaker:		$1^{3}/_{16}$" (3 cm) dynamic
Microphone:		Condenser microphone
Power Consumption:	Standby: Approx. 5 W Maximum: Approx. 7 W	
Dimensions (H X W X D):	$3^{5}/_{32}$" x $4^{29}/_{32}$" x $8^{9}/_{32}$" (80 × 125 × 210mm)	$10^{15}/_{16}$" x $2^{1}/_{8}$" x $1^{3}/_{16}$" (278 × 54 × 40mm)
Weight:	0.66 lbs. (300 g)	0.42 lbs. (190g) with battery

Design and specifications are subject to change without notice.

IMPORTANT INFORMATION ABOUT LEAD FREE, (PbF), SOLDERING

If lead free solder was used in the manufacture of this product the printed circuit boards will be marked PbF.
Standard leaded, (Pb), solder can be used as usual on boards without the PbF mark.

When this mark does appear please read and follow the special instructions described in this manual
on the use of PbF and how it might be permissible to use Pb solder during service and repair work.

Panasonic

⚠ **WARNING**

This service information is designed for experienced repair technicians only and is not designed for use by the general public. It does not contain warnings or cautions to advise non-technical individuals of potential dangers in attempting to service a product. Products powered by electricity should be serviced or repaired only by experienced professional technicians. Any attempt to service or repair the product or products dealt with in this service information by anyone else could result in serious injury or death.

When you note the serial number, write down all 11 digits. The serial number may be found on the bottom of the unit.

FOR SERVICE TECHNICIANS

ICs and LSIs are vulnerable to static electricity.
When repairing, the following precautions will help prevent recurring malfunctions.
1. Cover plastic parts boxes with aluminum foil.
2. Ground the soldering irons.
3. Use a conductive mat on worktable.
4. Do not grasp IC or LSI pins with bare fingers.

CONTENTS

1 ABOUT LEAD FREE SOLDER (PbF: Pb free)

Note:

In the information below, Pb, the symbol for lead in the periodic table of elements, will refer to standard solder or solder that contains lead.

We will use PbF solder when discussing the lead free solder used in our manufacturing process which is made from Tin (Sn), Silver (Ag), and Copper (Cu).

This model, and others like it, manufactured using lead free solder will have PbF stamped on the PCB. For service and repair work we suggest using the same type of solder although, with some precautions, standard Pb solder can also be used.

Caution

- PbF solder has a melting point that is 50°F ~ 70° F (30°C ~ 40°C) higher than Pb solder. Please use a soldering iron with temperature control and adjust it to 700°F ± 50° F (370°C ± 10°C). In case of using high temperature soldering iron, please be careful not to heat too long.
- PbF solder will tend to splash if it is heated much higher than its melting point, approximately 1100°F (600°C).
- If you must use Pb solder on a PCB manufactured using PbF solder, remove as much of the original PbF solder as possible and be sure that any remaining is melted prior to applying the Pb solder.
- When applying PbF solder to double layered boards, please check the component side for excess which may flow onto the opposite side (See the figure below).
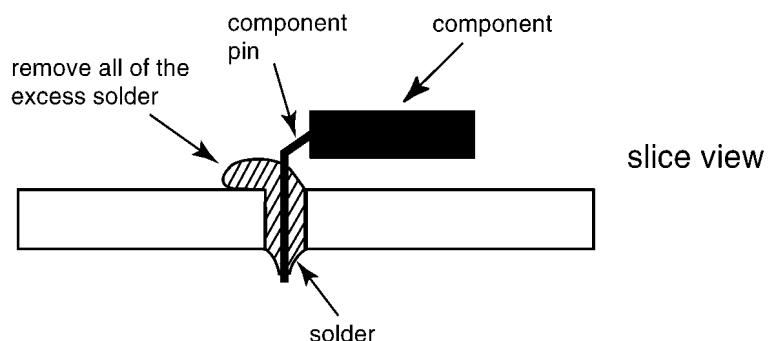
1.1. Suggested PbF Solder

There are several types of PbF solder available commercially. While this product is manufactured using Tin, Silver, and Copper (Sn+Ag+Cu), you can also use Tin and Copper (Sn+Cu), or Tin, Zinc, and Bismuth (Sn+Zn+Bi). Please check the manufacturer's specific instructions for the melting points of their products and any precautions for using their product with other materials.

The following lead free (PbF) solder wire sizes are recommended for service of this product: 0.3mm, 0.6mm and 1.0mm.

0.3mm X 100g	0.6mm X 100g	1.0mm X 100g

1.2.   How to recognize that Pb Free solder is used

1.2.1.   Base Unit Main PCB

Marked

(Component View)
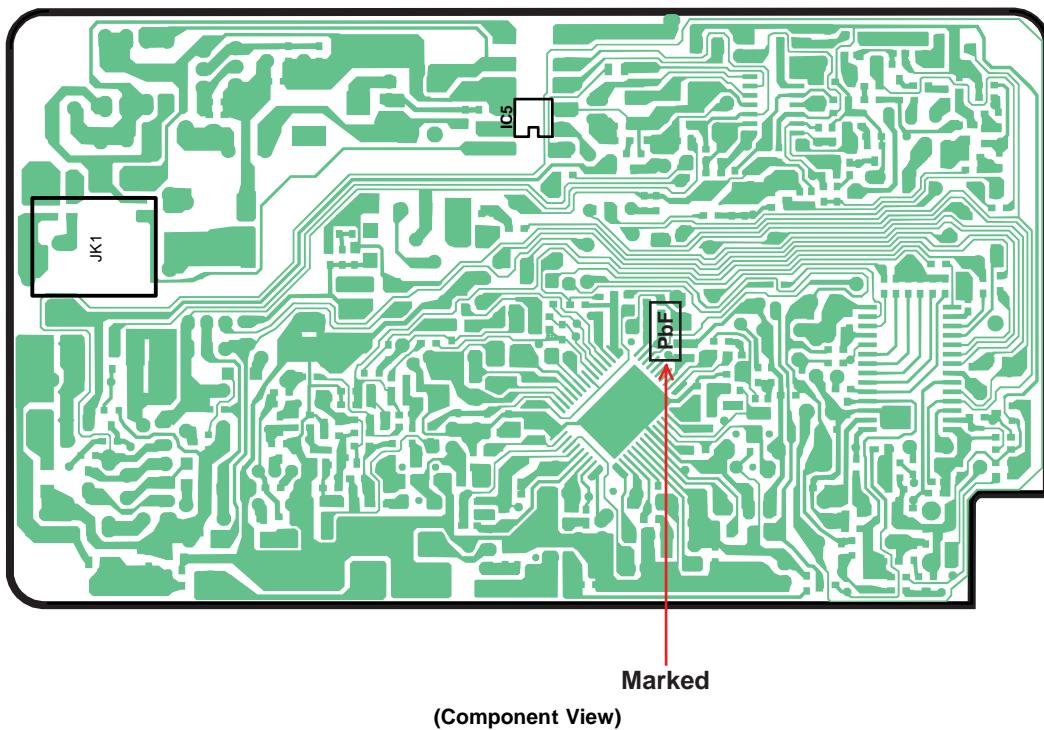
Note:

The location of the "PbF" marks is subject to change without notice.

1.2.2.   Handset PCB

Marked

(Component View)

Note:

The location of the "PbF" marks is subject to change without notice.

5
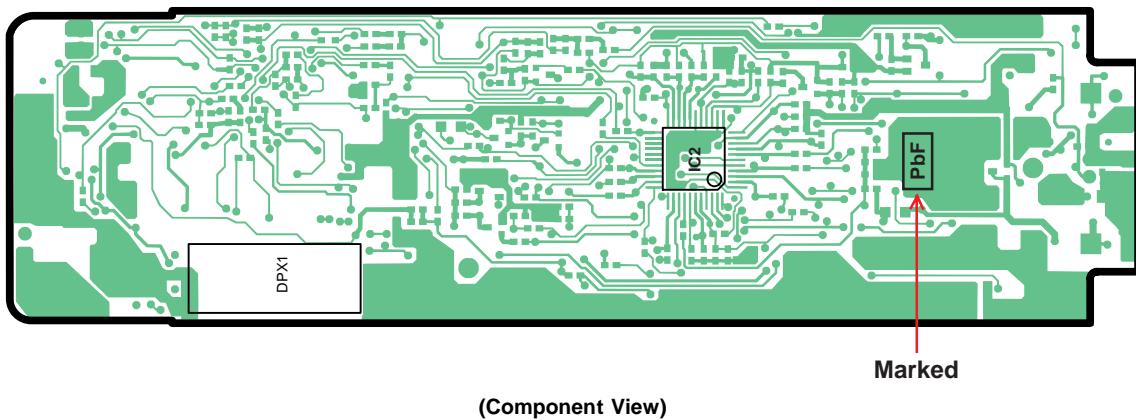
2 FOR SERVICE TECHNICIANS

ICs and LSIs are vulnerable to static electricity.

When repairing, the following precautions will help prevent recurring malfunctions.

1. Cover plastic parts boxes with aluminum foil.
2. Ground the soldering irons.
3. Use a conductive mat on worktable.
4. Do not grasp IC or LSI pins with bare fingers.

3 CAUTION

Danger of explosion if battery is incorrectly replaced.

Replace only with the same or equivalent type recommended by the manufacturer.

Dispose of used batteries according to the manufacturer´s Instructions.

4 BATTERY

4.1. Recharge

When the RECHARGE indicator flashes
or the unit beeps intermittently, place
the handset on the base unit for about
15 hours to recharge the battery.

RECHARGE
Indicator
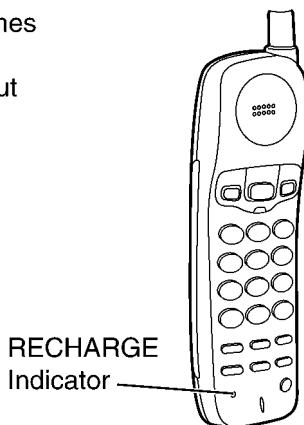
4.2. Battery information

After your Panasonic battery is fully charged:

Operation	Operating time
While in use (TALK)	Up to about 5 hours
While not in use (Standby)	Up to about 14 days

- The battery operating time may be shortened depending on usage conditions and ambient temperature.
- **As preventative maintenance, clean the handset and the base unit charge contacts with a soft, dry cloth once a month. Clean more often if the unit is subject to grease, dust or humidity.** Otherwise the battery may not charge properly.
- If the battery is fully charged, you do not have to place the handset on the base unit until the RECHARGE indicator flashes. This will maximize the battery life.
- The battery cannot be overcharged.

5 BATTERY REPLACEMENT

If the RECHARGE indicator flashes after being fully charged, replace the battery with a new Panasonic P-P301 (KX-A36A) battery.
When repalcing the battery, programmed information may be erased.
Reprogram if necessary.
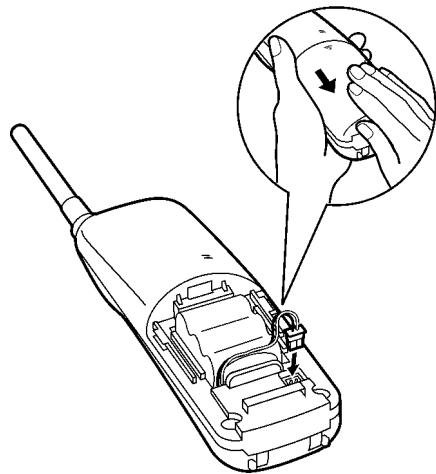
1 Press the notch on the battery cover firmly and slide it as indicated by the arrow.

2 Replace the battery and close the cover.

3 Make sure to charge the new battery for about 15 hours.

8

6 LOCATION OF CONTROLS

6.1. Base Unit

Antenna

Handset Hook

IN USE/CHARGE
Indicator

HANDSET LOCATOR
Button

Charge
Contacts

6.2. Handset

Antenna

TALK Button and
Indicator

AUTO Button

DIRECT Button

RECALL
Button

RINGER Button

REDIAL Button

PROGRAM Button

PAUSE Button

LOUD Button

CH (Channel)
Button

RECHARGE
Indicator

Charge Contacts
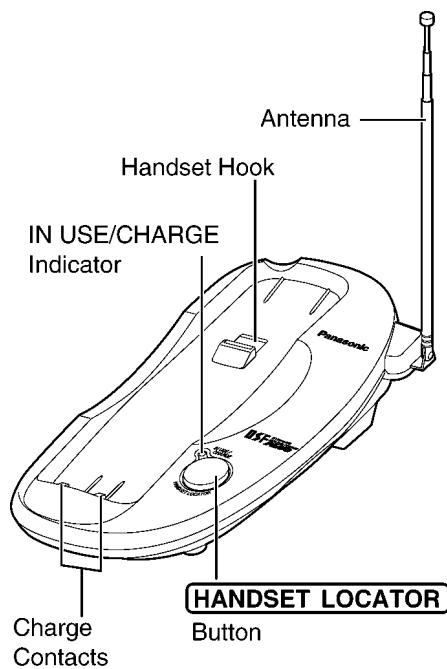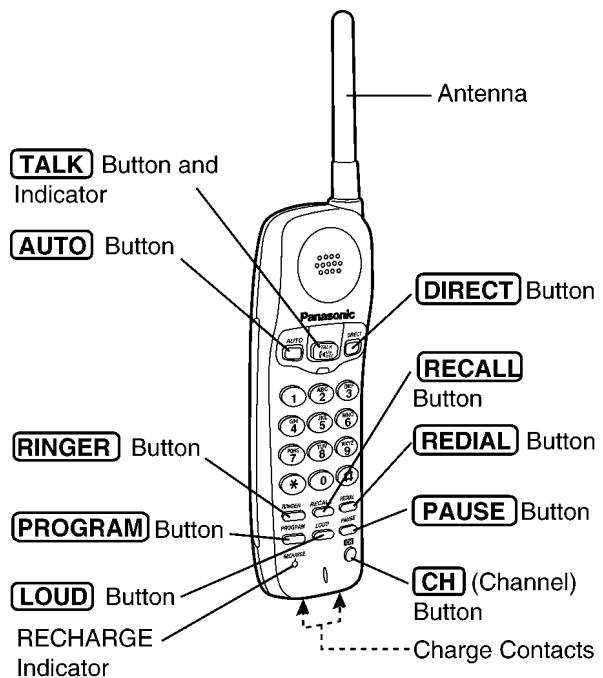
7 CONNECTION

1 Connect as shown.

Fasten the AC adaptor cord.
Hooks

To Single-Line
Telephone Jack

Telephone Line Cord

To Power Outlet
(AC 230 V–240 V,
50/60 Hz)

AC Adaptor

Extend the
antenna fully.
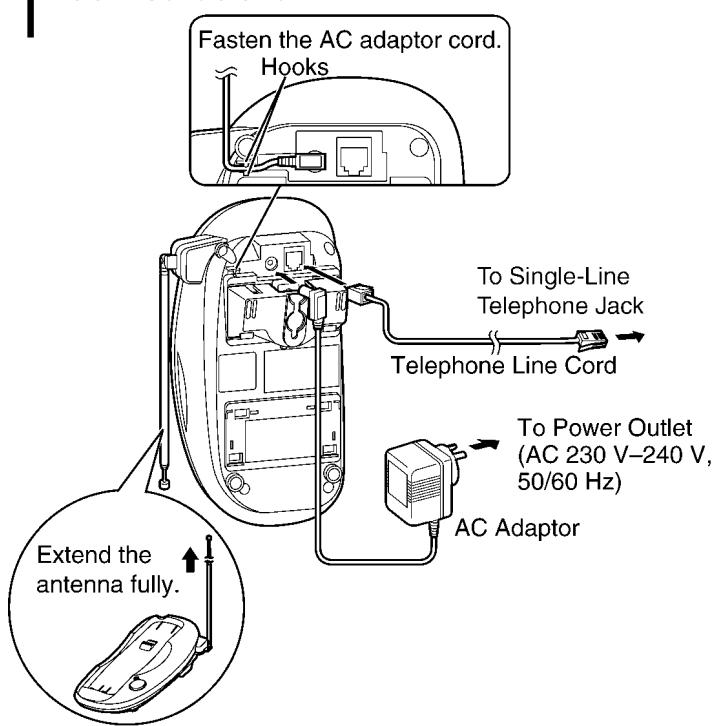
- USE ONLY WITH Panasonic AC ADAPTOR PQLV16AL.
- The AC adaptor must remain connected at all times.
  (It is normal for the adaptor to feel warm during use.)
- This unit will not function during a power failure.
  If you want to connect a standard telephone on the same line, use a T-adaptor.
- KX-TC2000NZ is not designed to be used with rotary (pulse dialling) services.

2 Install the battery in the handset, and close the handset cover, locking it into place.

Black Lead
Red Lead
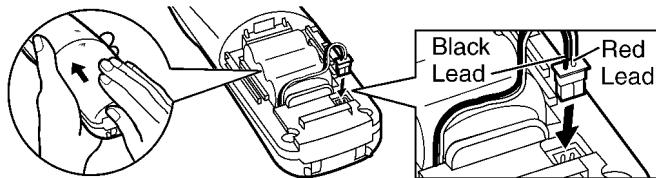
3 Charge the battery for about 15 hours.

STOP

• The IN USE/CHARGE indicator lights.

IN USE/CHARGE Indicator
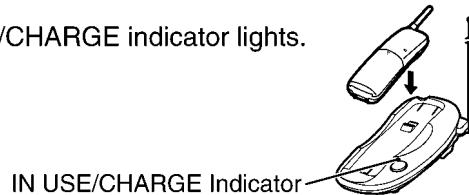
For Service Hint:

To select the dialing mode TONE
The TALK indicator light must be off before programming.

Press [PROGRAM] ➡ [AUTO] ➡ [*] twice (TONE) ➡ [AUTO].

• A beep sounds.
• To cancel during programming, press [PROGRAM], then restart from the beginning.
• If 3 beeps sound during programming, a wrong key was pressed. Start again from the beginning.

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8 OPERATIONS

8.1. Making Calls
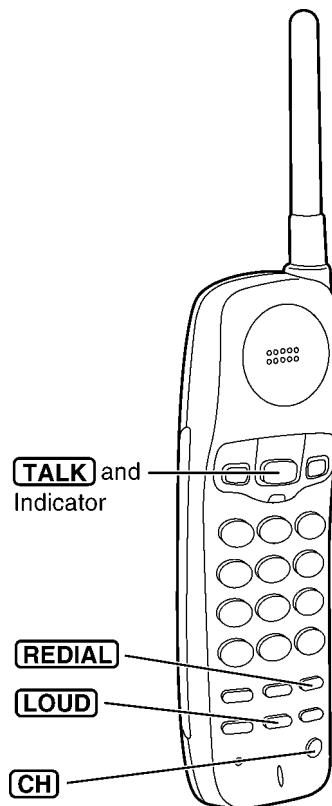
1 Press (TALK).
• The TALK indicator lights.

2 Dial a phone number.

3 To hang up,
press (TALK) or place the handset on the base unit.
• The indicator light goes out.

(TALK) and Indicator

(REDIAL)

(LOUD)

(CH)

To redial the last number dialed
Press (TALK) ➡ (REDIAL).

To select the handset receiver volume
Press (LOUD) while talking.
• Each time you press the button, the volume level will change to LOW (preset) or HIGH.

If noise interferes with the conversation
Press (CH) to select a clearer channel or move closer to the base unit.

Backlit handset keypad
The handset dialing buttons will light when you press a button or lift the handset off the base unit, or when a call is received. The lights will go out a few seconds after pressing a button, lifting the handset or answering a call.

8.2. Answering Calls

(TALK) and Indicator
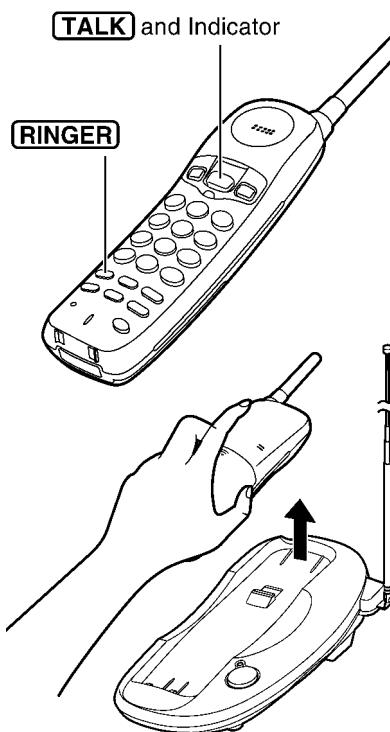
(RINGER)

If the handset is off the base unit,
press (TALK).
• You can also answer a call by pressing any dialing button (0) to (9), (✳) or (#) (—**Any Key Talk**).

OR

If on the base unit,
just lift up.

Selecting the ringer volume
The TALK indicator light must be off.

• **To select HIGH (preset) or LOW,**
press (RINGER).
Each time you press the button, the ringer volume will change and the selected volume will ring.

• **To turn the ringer OFF,**
press and hold (RINGER) until a beep sounds.

• **To turn the ringer ON,**
press (RINGER).

Additional Security Feature

In the event that a call cannot be made from the handset following a power interruption, disconnect the base unit from the line momentarily then reconnect it.
Turn the handset off, and replace it on the base unit.
This will re-establish the security system and the handset can be used as before.

8.3. Storing Phone Numbers in Memory

You can store up to 10 phone numbers. The dialing buttons ((0)) to ((9)) function as memory stations.
The TALK indicator light must be off before programming.
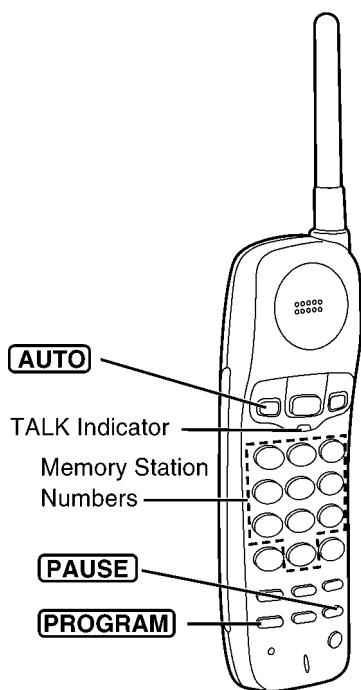
1 Press (PROGRAM).
• The TALK indicator flashes.

2 Enter a phone number up to 16 digits.

3 Press (AUTO).

4 Press a memory station number ((0) to (9)).
• A beep sounds.
• To store other numbers, repeat steps 1 through 4.

• If a pause is required for dialing, press (PAUSE) where needed. Pressing (PAUSE) counts as one digit.

AUTO
TALK Indicator
Memory Station Numbers
PAUSE
PROGRAM

If you misdial
Press (PROGRAM) to end storing. ➡
➡ Start again from step 1.

To erase a stored number
Press (PROGRAM) ➡ (AUTO) ➡
➡ the memory station number ((0) to (9)) for the phone number to be erased.
• A beep sounds.

8.4. Storing a Phone Number in the DIRECT Button

A phone number stored in the (DIRECT) button can be dialed with a one-touch operation.
The TALK indicator light must be off before programming.
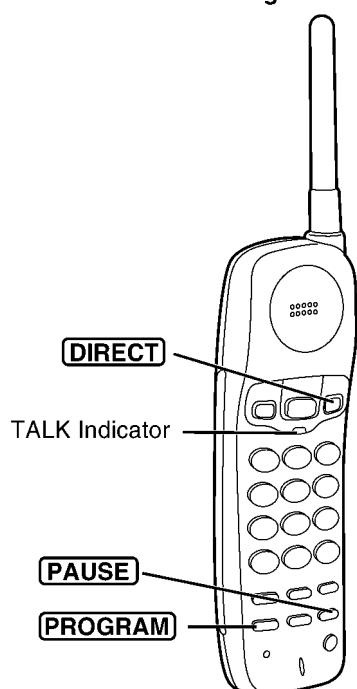
1 Press (PROGRAM).
• The TALK indicator flashes.

2 Enter a phone number up to 16 digits.

3 Press (DIRECT).
• A beep sounds.

• If a pause is required for dialing, press (PAUSE) where needed. Pressing (PAUSE) counts as one digit.

DIRECT
TALK Indicator
PAUSE
PROGRAM

If you misdial
Press (PROGRAM) to end storing. ➡
➡ Start again from step 1.

To erase a stored number
Press (PROGRAM) ➡ (DIRECT).
• A beep sounds.

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8.5. Dialing a Stored Number
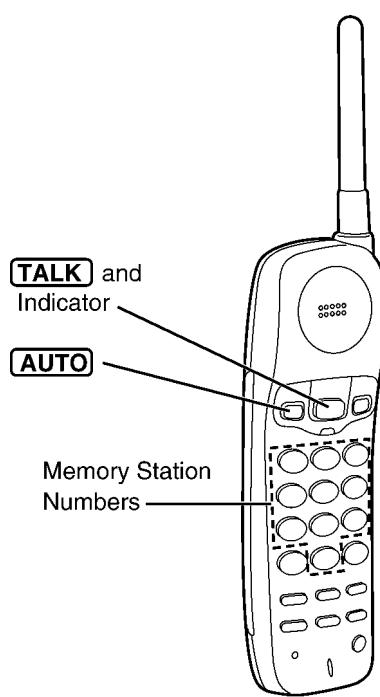
1 Press (TALK).
• The TALK indicator lights.

2 Press (AUTO).
• The TALK indicator flashes.

3 Press the memory station number ((0) to (9)).
• The stored number is dialed.

(TALK) and Indicator

(AUTO)

Memory Station Numbers

8.6. Dialing the Stored Number in the DIRECT Button
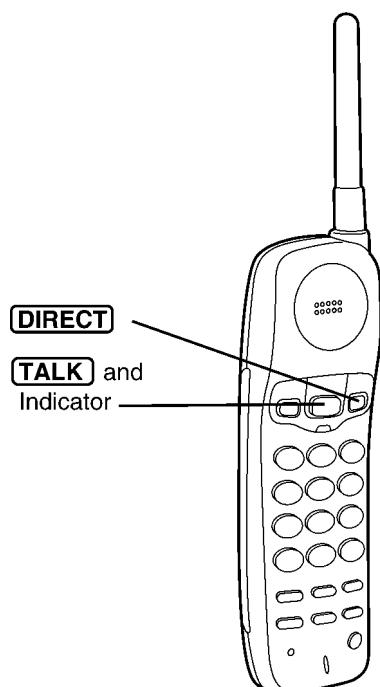
1 Press (TALK).
• The TALK indicator lights.

2 Press (DIRECT).
• The stored number is dialed.

(DIRECT)

(TALK) and Indicator

8.7.   Recall Button
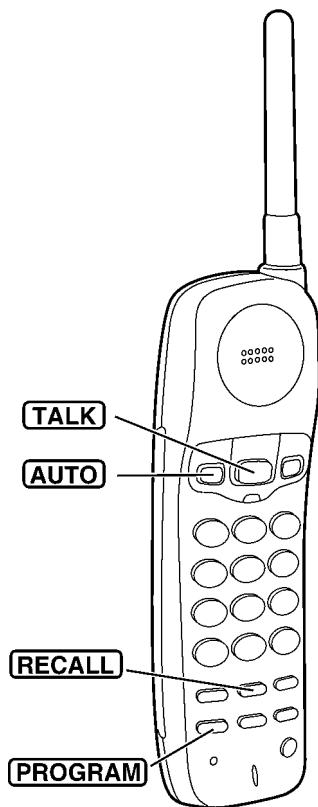
Pressing (RECALL) allows you to use special features of your host PBX such as transferring an extension call or accessing optional telephone services such as call waiting.

Selecting the recall time

The recall time depends on your telephone exchange or host PBX. You can select the following recall times; "90, 100, 110, 250, 300, 400, 600 or 700 msec (milliseconds)". Your phone comes from the factory set to "600 msec".
The (TALK) indicator light must be off before programming.

Press (PROGRAM) ➡ Dialing button ([1] to [8]) ➡ (AUTO) ➡
➡ (RECALL) .

[1]: 90 msec   [2]: 100 msec   [3]: 110 msec

[4]: 250 msec   [5]: 300 msec   [6]: 400 msec

[7]: 600 msec   [8]: 700 msec

- A beep sounds.
- If 3 beeps sound after programming, a wrong key was pressed. Start again from the beginning.
- If the unit is connected via a PBX, PBX functions (transferring a call etc.) might not work correctly. Consult your PBX supplier for the correct setting.
- When you receive a second call during a conversation, you will hear a signal tone following the call waiting tone and the conversation will be interrupted for approximately a second. The tones are generated from the telephone company. This is not fault of the product as these events are normal.

> Make sure the recall time is set to 600 msec for use with Telecom's Call Waiting Service. Press (RECALL) if you hear a call-waiting tone while talking.
> - The first call is put on hold and you can answer the second call.
> - To return to the first caller, press (RECALL) again.

9 DISASSEMBLY INSTRUCTIONS
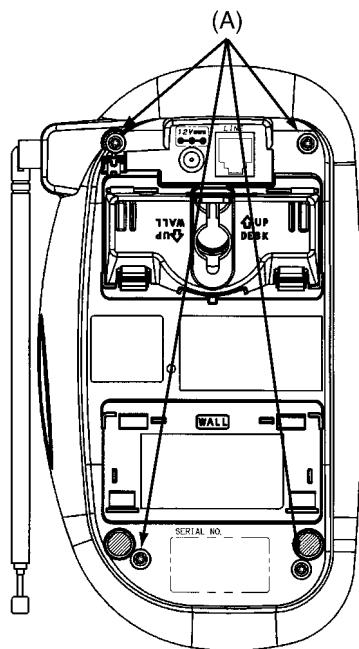
Fig. 1
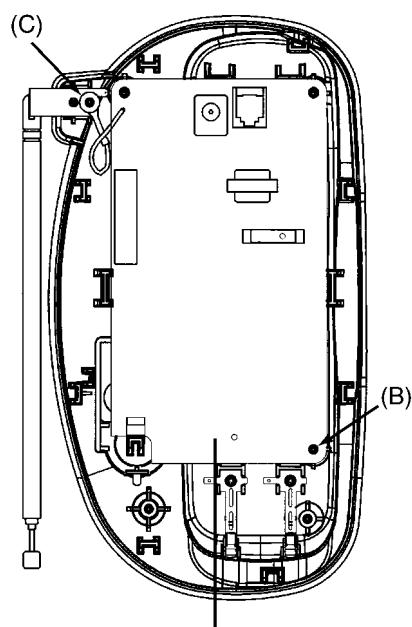
Fig. 2

Remove the P.C.Board.

Show in Fig.	Procedure	To remove.	Remove.
1	1	Lower Cabinet	Screws (2.6 × 12)........................ (A) × 4
2	1, 2	Main P.C. Board	Screw (2.6 × 6)........................... (B) × 1
			Screw (2.6 × 12)........................... (C) × 1
			Solder
			Main P.C. Board.

Black Lead
Red Lead

Fig. 3

(D)

Fig. 4

(E)

Remove the P.C.Board.

Fig. 6

Insert a JIG (PQDJ10006Y) between the Front and the Rear Cabinet, then pull it along the gap to open the Cabinet.

Likewise, open the other side of the Cabinet.

Rear Cabinet

Remove the Rear Cabinet by pushing it upward.
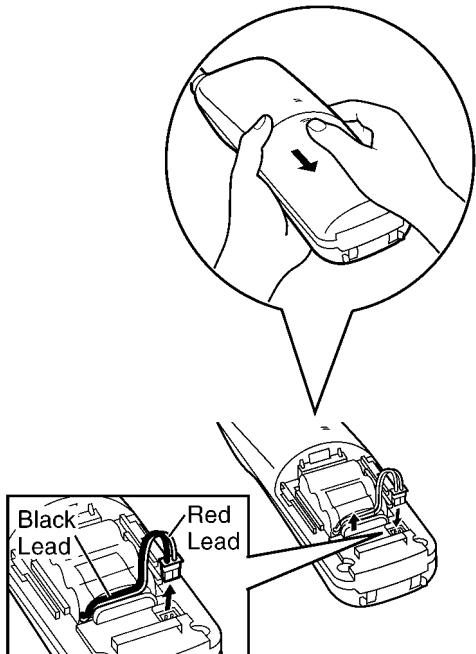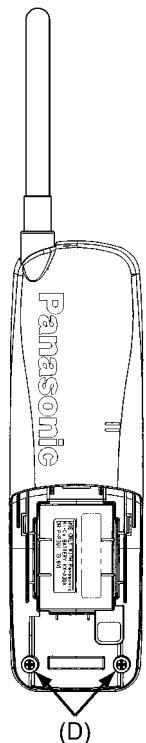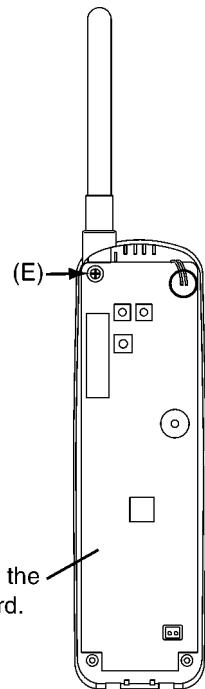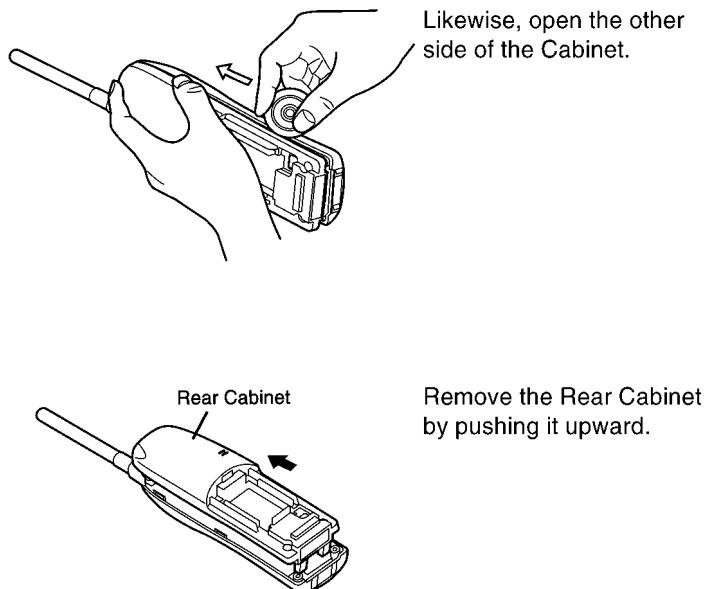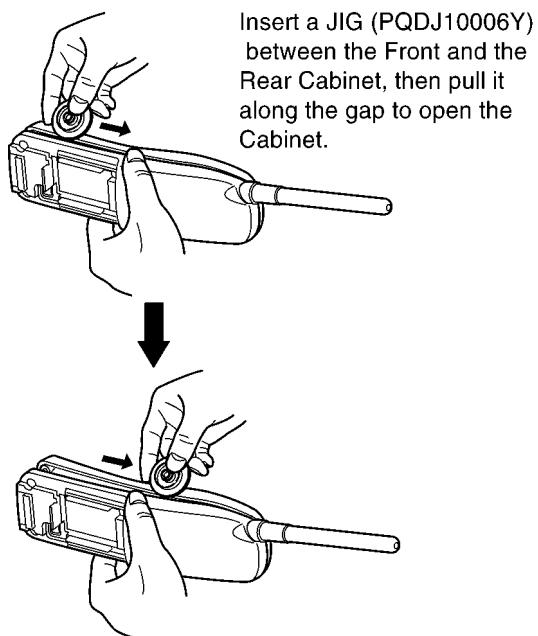
Fig.5

Show in Fig.	Procedure	To remove.	Remove.
3	3	Rear Cabinet	Battery compartment cover.
4	3, 4		Screws (2.6 × 12).....................(D) × 2
5	3, 4, 5		Follow the procedure.
6	3, 4, 5, 6	Main P. C. Board	Screw (2.6 × 12).......................(E) × 1
			Tape and solder.
			Main P. C. Board.

10 TROUBLESHOOTING GUIDE

MAIN

Power on BASE UNIT	→ **Check Power**
OK ↓	
Bell	→ **Bell Reception**
OK ↓	
Link	

OK / Not Link

Battery Charge	→ **Check Battery Charge**
OK ↓	→ **Check Link**

Handset Voice Transmission	→ **Check Handset Transmission**
OK ↓	
Handset Voice Reception	→ **Check Handset Reception**
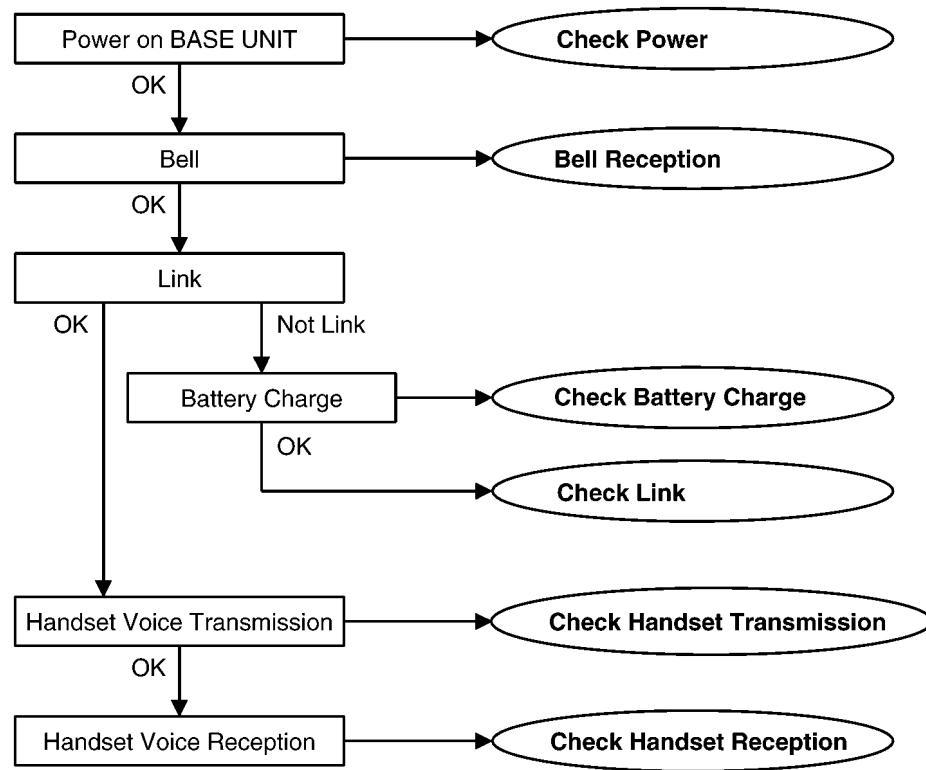
Cross Reference:

Check Power (P.19)

Bell Reception (P.20)

Check Battery Charge (P.21)

Check Link (P.22)

Check Handset Transmission (P.24)

Check Handset Reception (P.24)

10.1. Check Power

Base Unit
Is the AC Adaptor inserted into 230V - 240V outlet?
(AC Adaptor PQLV16ALZ)

| Is input of D6 12V or more? | NO → | Check **Reset Circuit (Base Unit)**. |

YES ↓   YES ↓

| Is the collector of Q18 4.5V or more? | NO | Check AC Adaptor. |

YES ↓

| Is CPU (VDD) 4.5V or more? | NO → | Check **Power Supply Circuit**. |

YES ↓

| Is CPU (RST) High? | NO |

YES ↓

| Does CPU (XOUT) oscillate at 7.952MHz? | NO → | Check X2, R153, C65 and C67. |

YES ↓

| Check CPU. |
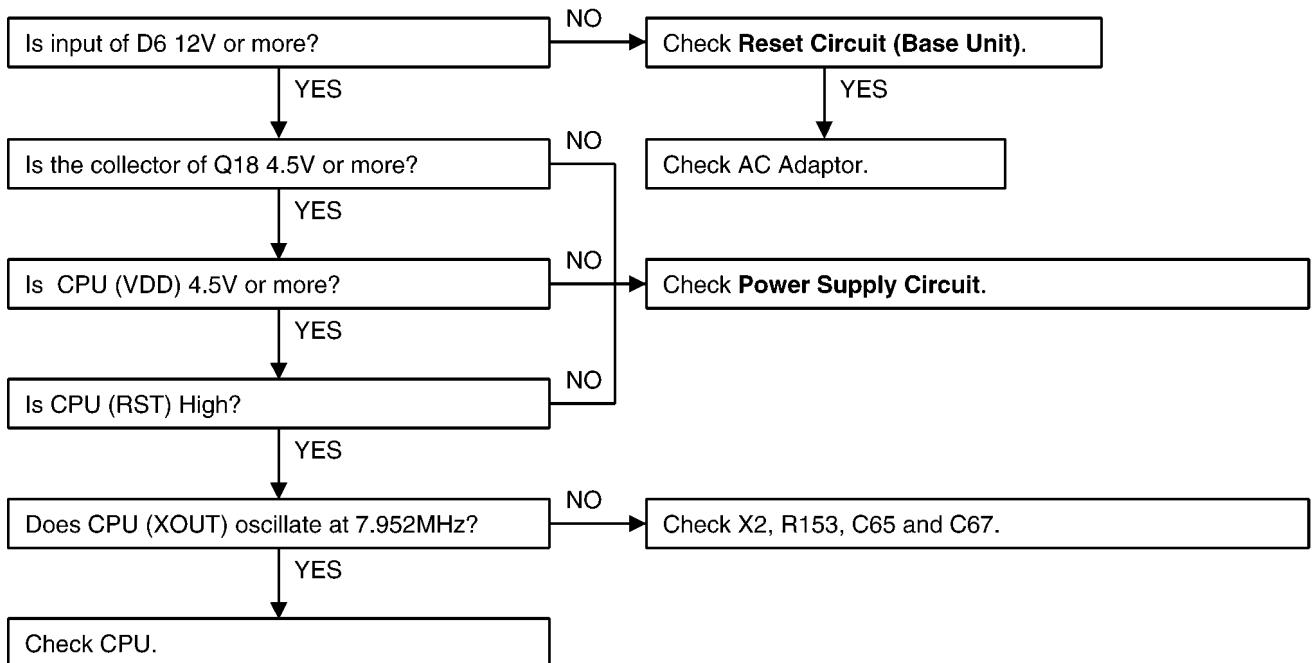
Cross Reference:
    Reset Circuit (Base Unit) (P.42)
    Power Supply Circuit (P.41)

Note:
    CPU: IC2

HANDSET

| Is the battery inserted to BATT1? |

↓

| Is VBAT (BATT1) 3.50V or more? | NO → | Check the battery. |

YES ↓

| Is CPU (VDD) 3.0V or more? | NO → | Check **Charge Circuit**. |
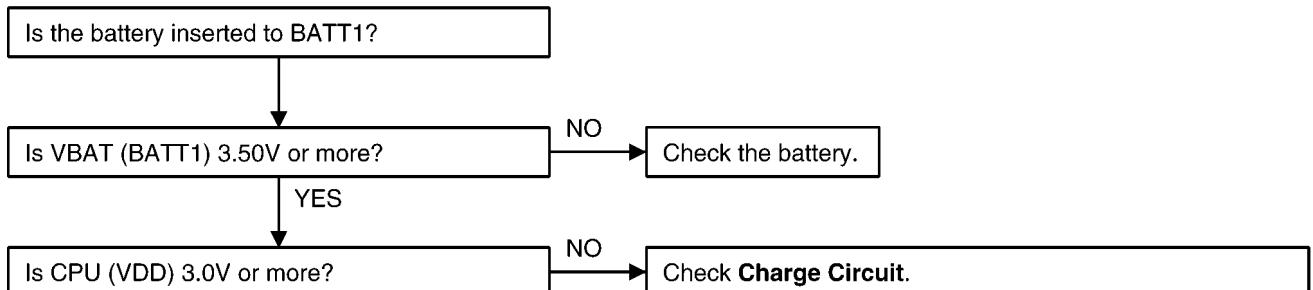
Cross Reference:
    Charge Circuit (P.43)

Note:
    CPU: IC2

*: Each measurement points are shown in **CIRCUIT BOARD (Base Unit)** (P.67) or **CIRCUIT BOARD (Handset)** (P.69)

10.2. Bell Reception

Base Unit

| Is the bell signal found at IC3D (14) while the bell is ringing? | NO → | Check **Telephone Line Interface.** |

YES ↓

| Is the bell signal found at CPU (RingDET) while the bell is ringing? | NO → | Check Q20, R146, R148, R149 and C97. |

YES ↓

| Is there CPU (TX DATA)* (square wave form)? | NO → | Check CPU and X2. |

YES ↓

| Check link in **7.4. Check Link**. |
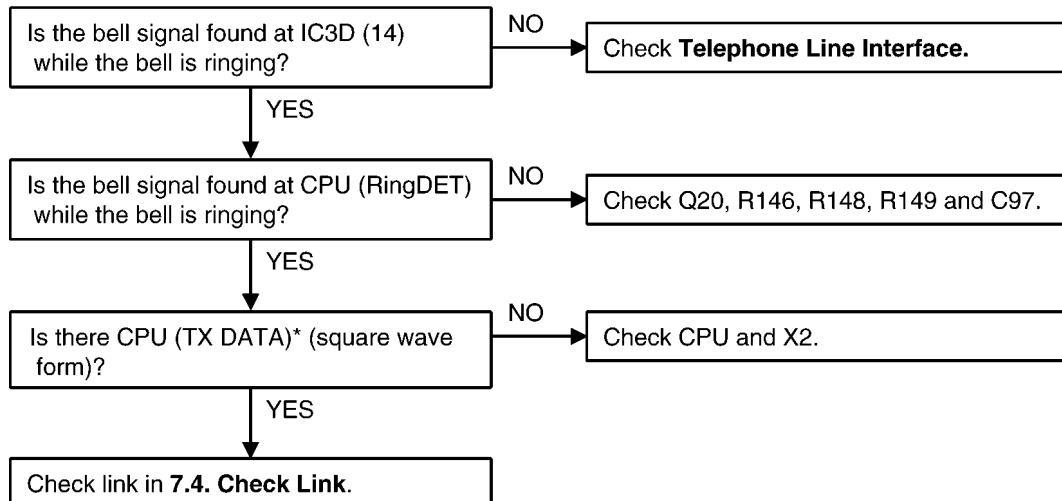
Cross Reference:

    Check Link (P.22)

    Telephone Line Interface (P.43)

Note:

    CPU: IC2

HANDSET

| Does the battery save mode change to stand-by mode when the bell starts ringing? | NO → | Check R5, R6, R8, R68, C9, C16. |

YES ↓

| Check link in **Check Link**. |
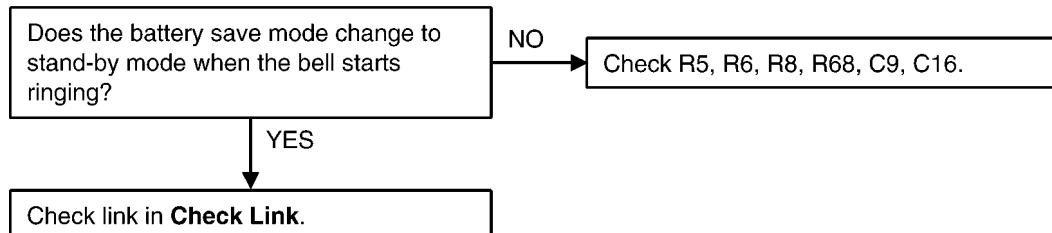
Cross Reference:

    Check Link (P.22)

*: Each measurement points are shown in **CIRCUIT BOARD (Base Unit)** (P.67) or **CIRCUIT BOARD (Handset)** (P.69)

10.3. Check Battery Charge

Base Unit

| Plug in the AC power source. |
| (AC Adaptor PQLV16ALZ) |
| Charge the Handset on the base unit. |

↓

Is the IN USE/CHARGE LED lit at charge state? —**NO**→ Check **Charge Circuit**.

↓ **YES**

Is the voltage of two charge contacts 0V and more than 10V from GND level? —**NO**→ Check **Power Supply Circuit**.

↓ **YES**

Is the collector of Q18 4.5V or more? —**NO**→ Check AC Adaptor, L8, L9, D6, R142, R145 and ZD8.

↓ **YES**

Is CPU (CHG DET)* high at charge state? —**NO**→ Check **Charge Circuit**.

↓ **YES**

Is CPU (CHG LD) low at charge state? —**NO**→ Check around CPU.

↓ **YES**

Check around LED1.

Cross Reference:
   Charge Circuit (P.43)
   Power Supply Circuit (P.41)

Note:
   CPU: IC2

HANDSET

Check BATT1.

↓

Is CPU (CHG DET) high at charge state? —**NO**→ Check **Reset Circuit (Handset)**.

↓ **YES**

Check **Reset Circuit (Handset)**.
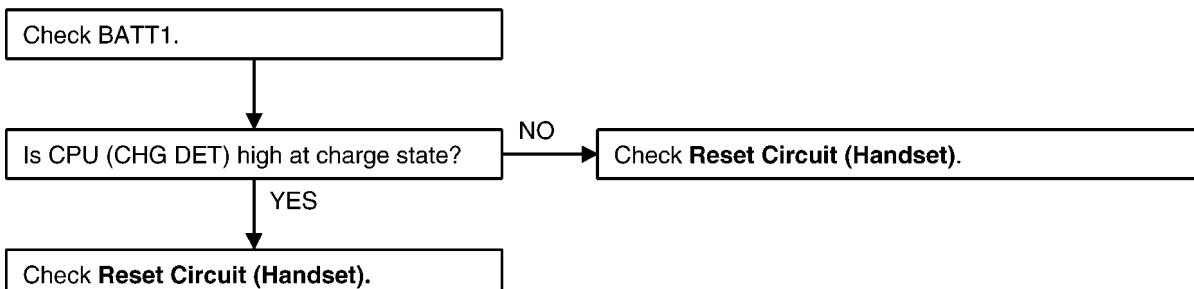
Cross Reference:
   Reset Circuit (Handset) (P.47)

Note:
   CPU: IC2

*: Each measurement points are shown in **CIRCUIT BOARD (Base Unit)** (P.67) or **CIRCUIT BOARD (Handset)** (P.69)

10.4. Check Link

BASE UNIT

Does the Base Unit make link with Handset (correctly working unit) after the jig is placed on the cradle for ID code check? — **YES** → Base unit is OK. Check Handset.

NO

Does the clock (X2) oscillate? — **NO** → Check around X2 and CPU soldering.

YES

RF IC (2nd Mix)*: 10.7MHz? when RF signal (CH3/60dBμV) is input from Antenna in Base Unit Test mode? — **NO** → Check around RX VCO circuit (L10) and CF1.

YES

RF IC (IF OUT): 450KHz? when RF signal (CH3/60dBμV) is input from Antenna in Base Unit Test mode? — **NO** → Check around CF2 and RF IC soldering.

YES

Is there RF IC (RX DATA) (square wave form) when the TALK button on Handset is pressed? — **NO** → Check R5, R8, R68, R83, C12, C18 and RF IC.

YES

Is there CPU (TX DATA) (square wave form) when the TALK button on Handset is pressed? — **NO** → Check around CPU and X2.

YES

Is there DV1 (TX DATA) (square wave form) when the TALK button on Handset is pressed? — **NO** → Check R84, R40, R44, R45, R48, R51, R52, C52 and C58.

YES

Is there RF transmission power in RF test mode (TX Power)**? — **NO** → Check T6, RF IC and DPX1.

YES

Check the adjustment value.

: Refer to **Adjustment (P.26)

Note:
CPU: IC2
RF IC: IC1

*: Each measurement points are shown in **CIRCUIT BOARD (Base Unit)** (P.67) or **CIRCUIT BOARD (Handset)** (P.69)

HANDSET

Does the Handset make link with Base Unit (correctly working unit) after it is placed on the cradle for ID code check?	**YES** → Handset is OK. Check Base Unit.

↓ **NO**

Is VBAT around 3.9V?	**NO** → Check around Battery Power Supply circuit.

↓ **YES**

Does clock (X1) oscillate?	**NO** → Check around X1 and RF IC soldering.

↓ **YES**

RF IC (2nd Mix)*: 10.7MHz? when RF signal (CH3/60dBμV) is input from Antenna in Handset Test mode?	**NO** → Check around RX VCO circuit (L6) and CF1.

↓ **YES**

RF IC (IF IN): 455KHz? when RF signal (CH3/60dBμV) is input from Antenna in Handset Test mode?	**NO** → Check around CF2 and RF IC soldering.

↓ **YES**

Is there CPU (TX DATA) (square wave form) when the TALK button on Handset is pressed?	**NO** → Check around CPU, X2.

↓ **YES**

Is there DV1 (TX DATA) (square wave form) when the TALK button on Handset is pressed?	**NO** → Check R107, R42, R45, R46, R48, R51, R98, C53 and C58.

↓ **YES**

Is there RF transmission power in RF test mode (TX Power)**?	**NO** → Check around T6, DV1, RF IC and DPX1.

↓ **YES**

Check the adjustment value.

BASE UNIT ↓ **YES**

Is there RF IC (DET OUT) (square wave form) when the TALK button on Handset is pressed?	**NO** → Check RF IC.

↓ **YES**

Is there RF IC (RX DATA) (square wave form) when the TALK button on Handset is pressed?	**NO** → Check R5, R6, R8, R68, C9 and C16.

↓ **YES**

Check around CPU, X2 and X3.

: Refer to **Adjustment (P.29).

Note:
CPU: IC2
RF IC: IC1

*: Each measurement points are shown in **CIRCUIT BOARD (Base Unit)** (P.67) or **CIRCUIT BOARD (Handset)** (P.69)

10.5. Check Handset Transmission

```
┌─────────────────────────────────┐
│ Check MIC of HANDSET.           │
└─────────────────────────────────┘
                 │ YES
                 ▼
┌─────────────────────────────────┐
│ Check HANDSET TX in Signal Route.│
└─────────────────────────────────┘
```

Cross Reference:

  Signal Route (P.46)

10.6. Check Handset Reception

```
┌─────────────────────────────────┐
│ Check Speaker of HANDSET.       │
└─────────────────────────────────┘
                 │ YES
                 ▼
┌─────────────────────────────────┐
│ Check HANDSET RX in Signal Route . │
└─────────────────────────────────┘
```
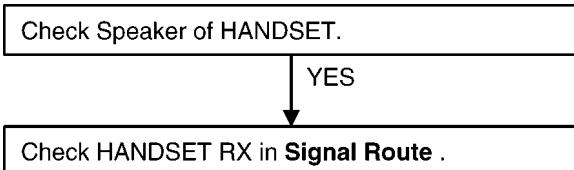
Cross Reference:

  Signal Route (P.46)


  *: Each measurement points are shown in **CIRCUIT BOARD (Base Unit)** (P.67) or **CIRCUIT BOARD (Handset)** (P.69)

11 ADJUSTMENTS (BASE UNIT)

If your unit have below symptoms, adjust or confirm each item using remedy column from the table.

Symptom	Remedy*
The base unit dose not respond to a call from handset.	Make confirmation in item (**A**)
The base unit dose not transmit or the transmit frequency is off.	Make adjustments in item (**B**)
The transmit frequency is off.	Make adjustments in item (**C**)
The transmit power output is low, and the operating distance between the base unit and the handset is less than normal.	Make adjustments in item (**D**)
The reception sensitivity of base unit is low with noise.	Make confirmation in item (**E**)
The transmit level is high or low.	Make confirmation in item (**F**)
The reception level is high or low.	Make confirmation in item (**G**)
The unit does not link.	Make confirmation in item (**H**)

*: Refer to **Adjustment** (P.26).

11.1. Test Mode Flow Chart (Base Unit)

The operation-flow of Test mode and main check items are shown below.

```
┌──────────────┐
│  Power OFF   │
└──────────────┘
       │          • Power on while pressing "LOCATOR" key.
       ▼
┌──────────────┐
│  Stand-by    │
└──────────────┘
       │          • Push "LOCATOR" key 4 items.
       ▼
┌──────────────┐
│    TALK      │
│   (ch 3)     │
└──────────────┘
                  • Check RF characteristics**
```
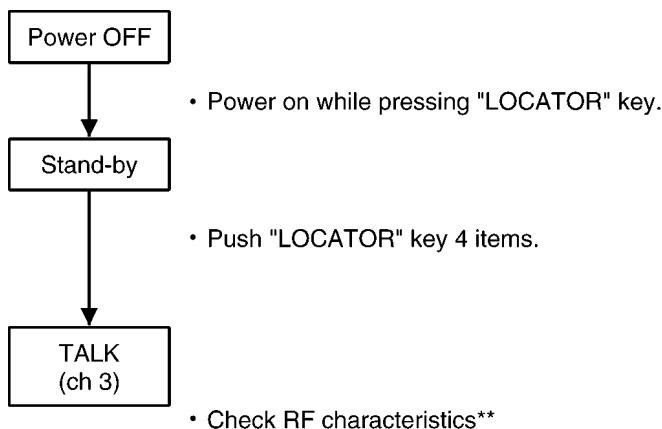
Note:

**: Refer to the above table.

25

11.2. How to change the channel

When RING DET and GND is short, the channel will be changed as follows;

CH3 → CH4 → CH6 → CH5 → CH7 → CH8 → CH9 → CH10 → CH1 → CH2
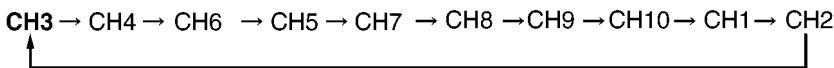
*: Refer to **Flow Solder Side View** (P.68).

11.3. Adjustment

	Adjustment Items	Test Mode	Adjustment Point	*Procedure	Check or Replace Parts
(**A**)	RX VCO Confirmation	3ch Talk	-	● Confirm so that the reading of the Digital Voltmeter is 2.0V ± 1.0V.	IC1, L10, C26, R14
(**B**)	TX VCO Adjustment	3ch Talk	T6	● Adjust T6 so that the reading of the Digital Voltmeter is 2.0V ± 0.3V.	IC1, DV1, T6
(**C**)	TX Frequency Adjustment	3ch Talk	VC1	● Adjustment VC1 so that the reading of the frequency counter is 30.1750MHz ± 100Hz.	IC, X1, T6, DV1, C35, C40, VC1
(**D**)	TX Power Adjustment	3ch Talk	T5	● Adjust T5 so that the reading of the RF VTVM is more than 9dBm.	IC1, Q3, Q4, Q5, T5, DPX1
(**E**)	RX Sensitivity Confirmation (2nd IF output)	3ch Talk	T2	1. Apply 60dBuVemf output from S.S.G. (modulation frequency 1KHz, dev. 0KHz). 2. Confirm that the reading of RF VTVM is the maximum value (more than 20mV)	DPX1, T2, CF1, CF2
(**F**)	Line Output Level Confirmation	3ch Talk	-	1. Apply 60dBuVemf output from S.S.G. (modulation frequency 1KHz, dev. 3KHz). 2. Confirm that the reading of AF VTVM is more than 120mV (600Ω load).	IC1, Q11
(**G**)	Line Input Modulation Confirmation	3ch Talk	-	1. Input via loop simulator 1.0KHz, -20dBm (measured at T-R) signal. 2. Apply 60dBuVemf output from S.S.G. (modulation frequency 1KHz, dev. 0KHz). 3. Confirm so that the reading of FM Deviation Meter is 2.8KHz ± 0.3KHz.	IC1, DV1
(**H**)	Noise Squelch Confirmation	3ch Talk	-	1. Measure the SSG output level when the noise squelch changes from Low to High. 2. Confirm that the SSG output level is -10 ~ +5dBuVemf.	IC1, DPX1

* : The connection of adjustment equipment are as shown in **Adjustment Standard (Base Unit)** (P.27).

SSG Frequency: 39.875 MHz

11.4. Adjustment Standard (Base Unit)

When connecting the Simulator and Equipments for checking, please refer to the illustration below.
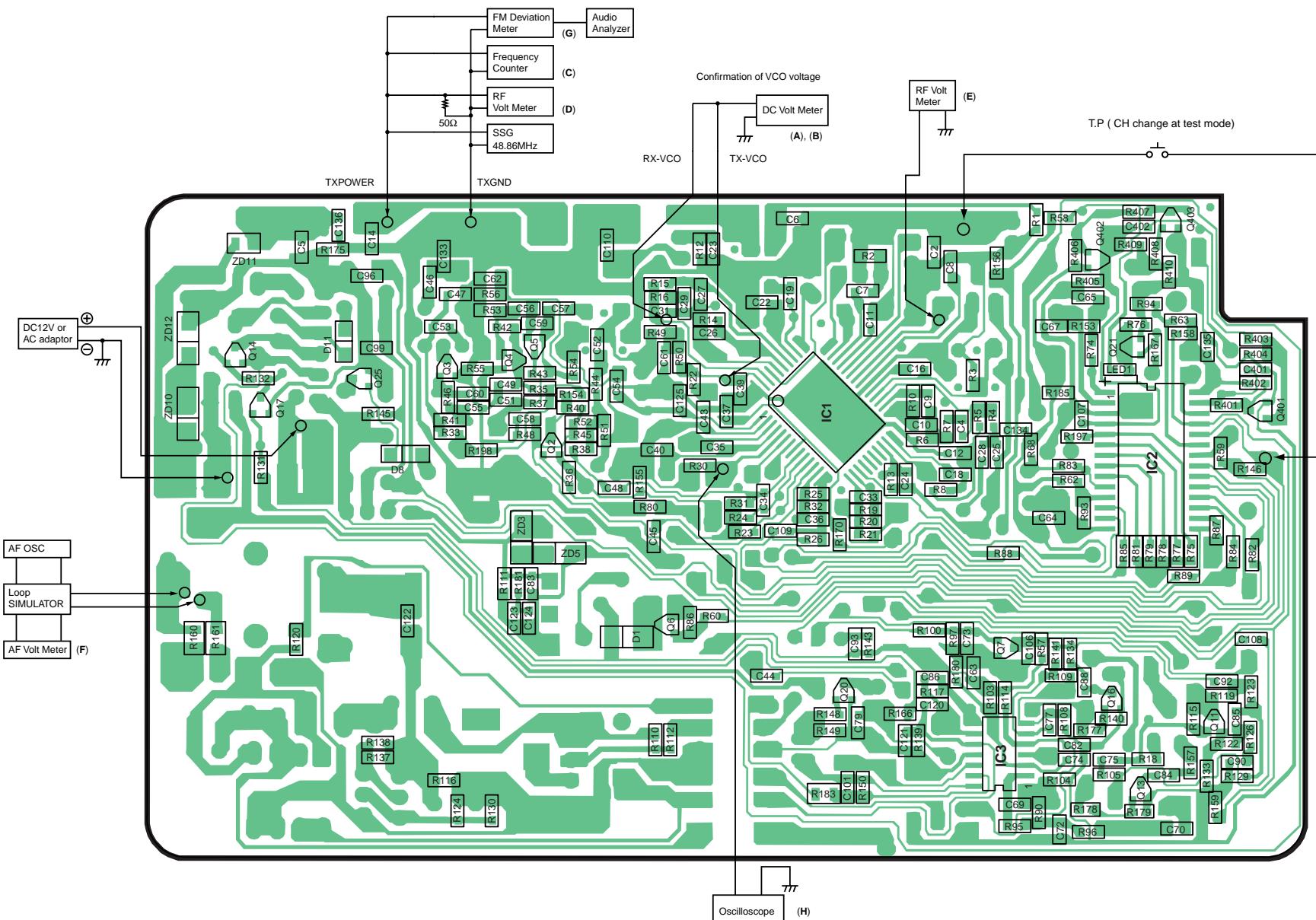
Note: **(A) - (H)** is refered to **ADJUSTMENTS (BASE UNIT)** (P.25)

12 ADJUSTMENTS (HANDSET)

If your unit have below symptoms, adjust or confirm each item using remedy column from the table.

Symptom	Remedy*
The movement of Battery Low Indicator is wrong.	Make confirmation in item (**A**)
The base unit does not respond to a call from the handset.	Make adjustments in item (**B**)
The base unit does not transmit or the transmit frequency is off.	Make confirmation in item (**C**)
The transmit frequency is off.	Make adjustments in item (**D**)
The transmit power output is low, and the operating distance between the base unit and the Handset is less than normal.	Make confirmation in item (**E**)
The reception sensitivity of the handset is low with noise.	Make confirmation item (**F**)
Does not link between the base unit and the handset.	Make confirmation in item (**G**)
The reception level is high or low.	Make confirmation item (**H**)
The transmit level is high or low.	Make confirmation in item (**I**)

*: Refer to **Adjustment** (P.29).

Unit condition:

1. Remove the antenna lead wire from P.C Board of the handset.

2. Power Supply: DC 3.9V (DC power supply)

3. Volume: HIGH (When P.C. Board of handset is in test mode, volume condition is medium. Press "LOCATOR" key once.)

4. Speaker Load: 150Ω

CH	TX Frequency	RX Frequency
CH3	39.875MHz	30.175MHz

12.1. Test Mode Flow Chart (Handset)

```
        ┌──────────────┐
        │  Power OFF   │
        └──────┬───────┘
               │         Insert the battery while pressing "5" key.
               ▼
        ┌──────────────┐
        │ Stand-by (3CH)│
        └──────┬───────┘
               │         Press "3" key.
               ▼
   ┌──→ ┌──────────────┐
   │    │  TALK (3CH)  │
   │    └──────┬───────┘
   │           │         Press "5" key.
   │           ▼
   │    ┌──────────────┐
   │    │ Stand-by (3CH)│
   │    └──────┬───────┘
   │           │         Press "3" key.
   └───────────┘
```
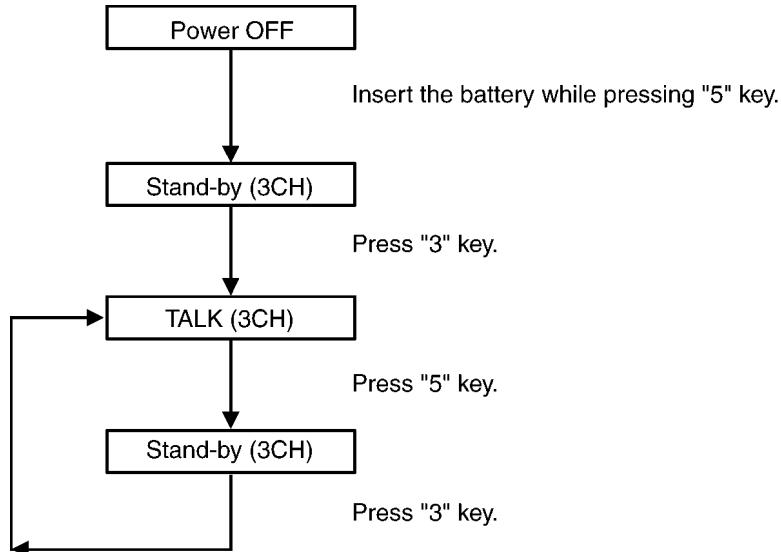
Note:

Refet to **CIRCUIT BOARD (Handset)** (P.69)

Signal Route (P.46)

12.2. How to change the channel

- Press ✱ button.

CH3 → CH4 → CH6 → CH5 → CH7 → CH8 → CH9 → CH10 → CH1 → CH2
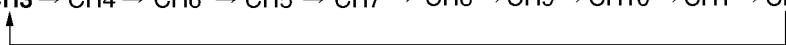
- Press # button.

CH3 → CH2 → CH1 → CH10 → CH9 → CH8 → CH7 → CH5 → CH6 → CH4

12.3. Adjustment

	Adjustment Items	Test Mode	Adjustment Point	Procedure	Check or Replace Parts
(A)	Battery Low Confirmation	3ch Talk	-	1. Adjust the power supply voltage to DC3.60V, and confirm so that the reading of oscillosope is High. 2. Adjust that power supply voltage to DC 3.40V, and confirm so that the reading of oscilloscope is Low.	IC1
(B)	TX VCO Adjustment	3ch Talk	T6	1. Adjust T6 so that the reading of the Digital Voltmeter is 1.5V ± 0.3V.	IC1, X1, T6, DV1
(C)	RX VCO Confirmation	3ch Talk	-	1. Confirm so that the reading of the Digital Voltmeter is 0.7 ~ 3.0V.	IC1, X1, L6, C24
(D)	TX Frequency Adjustment	3ch Talk	VC1	• Adjust VC1 so that the reading of the frequency counter is 39.8750MHz ± 100Hz.	IC1, DPX1, T5
(E)	TX Power Confirmation	3ch Talk	-	• Confirm so that the reading of the RF VTVM is more than -3.0dBm (50Ω load).	IC1,Q3,Q4, Q5, DPX1
(F)	RX Sensitivity Confirmation (2nd IF output)	3ch Talk	T3	1. Apply 60dBuVemf output from S.S.G. (modulation frequency 1KHz, dev. 0KHz). 2. Confirm that the reading of RF VTVM is the maximum value (more than 15mV).	DPX1, T3,IC1, CF1, CF2
(G)	Noise Squelch Confirmation	3ch Talk	-	1. Measure the SSG output level when the noise squelch changes from Low to High. (modulation frequency 1KHz, dev.3kHz) 2. Confirm that the SSG output level is -18 ~ 0dBuVemf.	IC1, DPX1
(H)	Speaker Output Level Confirmation	3ch Talk	-	1. Apply 60dBuVemf output from S.S.G. (modulation frequency 1KHz, dev. 3KHz). 2. Confirm that the reading of AF VTVM is more than 30mV. (distortion: less than 5%) (volume High).	IC1
(I)	Mic Modulation Factor Confirmation	3ch Talk	-	1. Apply a MIC signal (1KHz, 5.0mV at 600Ω load). 2. Confirmation so that the reading of FM Deviation Meter is 3.4KHz ± 0.4KHz.	IC1, DV1
(J)	Data Modulation Confirmation	3ch Talk	-	• Confirm for 5.0 ± 1.0KHz FM Deviation Meter reading.	
(K)	Battery low Confirmation	-	-	1. Apply 3.50V between BATT(+) and BATT(-). 2. Confirm that there is no flashing of RECHARGE LED. 3. Apply 3.40V between BATT(+) and BATT(-). 4. Confirm that there is flashing of RECHARGE LED.	IC1

The connections of adjustment equipment are as shown in **Adjustment Standard (Handset)** (P.30).

SSG Frequency: 30.175 MHz

12.4. Adjustment Standard (Handset)

When connecting the Simulator and Equipments for checking, please refer to the illustration below.

(Component View)
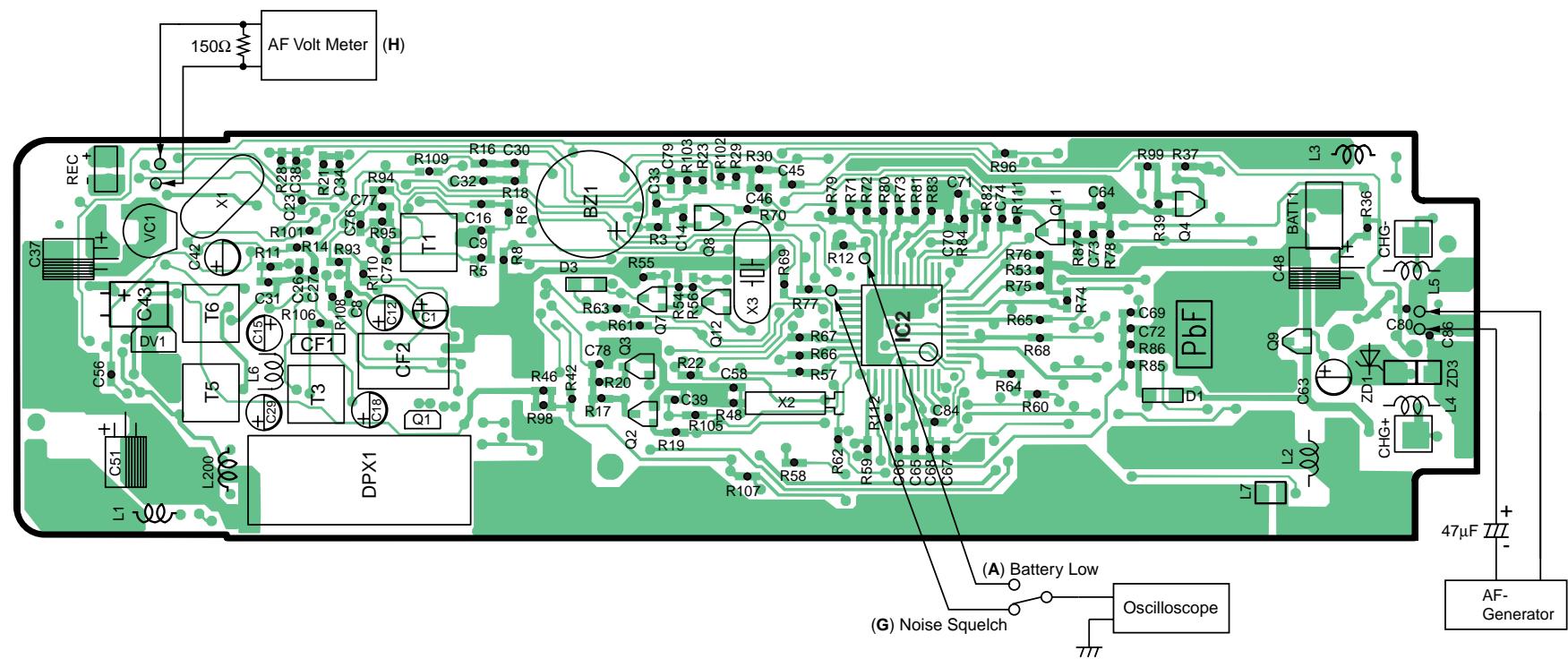
Note: (**A**) - (**I**) is refered to **ADJUSTMENTS (HANDSET)** (P.28)

(Flow Solder Side View)

Note: (**A**) - (**I**) is refered to **ADJUSTMENTS (HANDSET)** (P.28)

KX-TC2000NZB / KX-TC2000NZW / KX-TC2000NZF
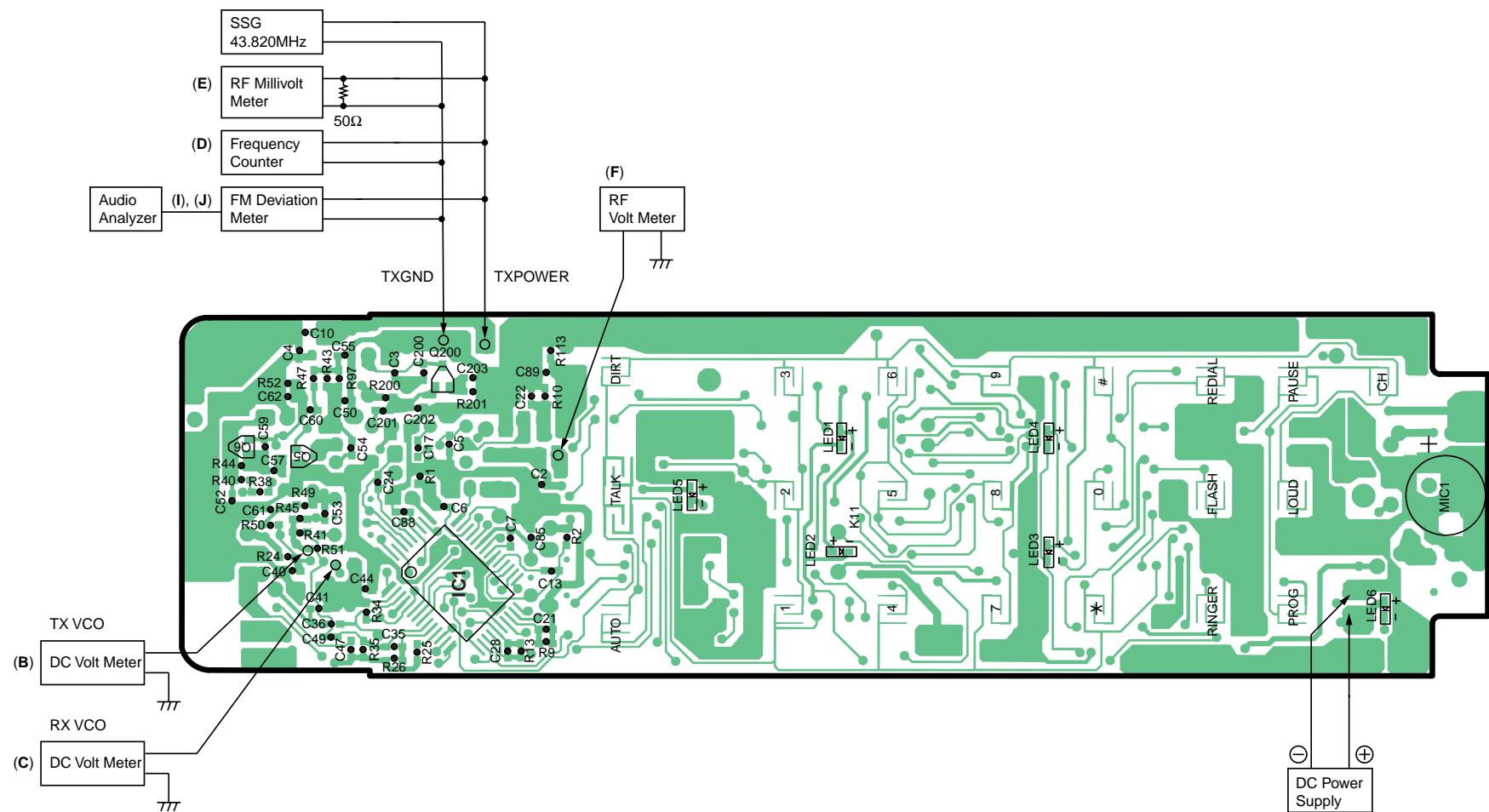
13 RF SPECIFICATION

13.1. Base Unit

Item	Value	Refer to -.*	Remarks
TX Frequency	30.175MHz ± 100Hz	**ADJUSTMENTS (BASE UNIT) (C)**	at CH3
TX Power	more than 1mW	**ADJUSTMENTS (BASE UNIT) (D)**	at CH3
Line Modulation factor	2.5 kHz~3.1 kHz	**ADJUSTMENTS (BASE UNIT) (G)**	
Data Modulation factor	4.5 kHz~7.5 kHz	—	
Line Output level	more than 120mV	—	

*: Refer to **Adjustment** (P.26).

13.2. Handset

Item	Value	Refer to -.**	Remarks
TX Frequency	39.875 MHz ± 0.1kHz	**ADJUSTMENTS (HANDSET) (D)**	at CH3
TX Power	more than 1mW	**ADJUSTMENTS (HANDSET) (E)**	at CH3 (Antenna soldering point 50Ω Load)
Data Modulation factor	5.0 kHz~6.0 kHz	**ADJUSTMENTS (HANDSET) (J)**	at CH3
MIC Modulation factor	2.9 kHz/dev~3.8 kHz/dev	**ADJUSTMENTS (HANDSET) (I)**	at CH3 (MIC terminal 2.4mV Input)
SP Output level	more than 30mV	—	

: Refer to **Adjustment (P.29).

14 HOW TO CHECK THE HANDSET SPEAKER

1. Prepare the digital voltmeter, and set the selector knob to ohm meter.

2. Put the probes at the speaker terminals as shown below.

32
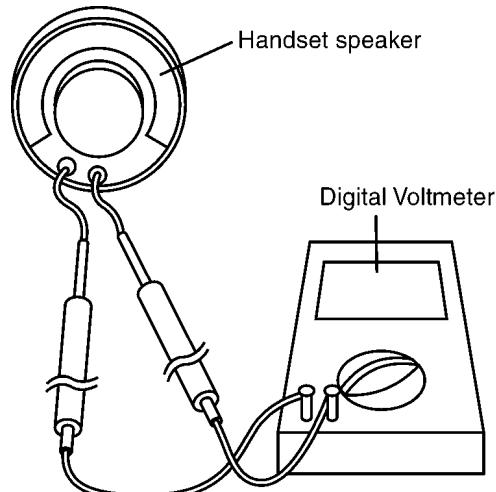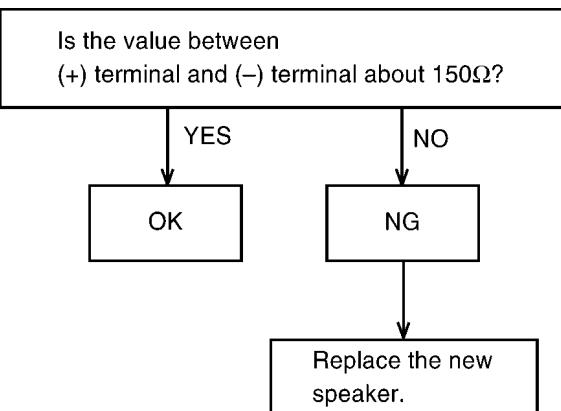
15 FREQUENCY TABLE (MHz)

Channel	BASE UNIT		PORTABLE UNIT	
	Transmit Frequency	Receive Frequency	Transmit Frequency	Receive Frequency
1	30.0750	39.7750	39.7750	30.0750
2	30.1250	39.8250	39.8250	30.1250
3	30.1750	39.8750	39.8750	30.1750
4	30.2250	39.9250	39.9250	30.2250
5	30.2750	39.9750	39.9750	30.2750
6	30.1000	39.8000	39.8000	30.1000
7	30.1500	39.8500	39.8500	30.1500
8	30.2000	39.9000	39.9000	30.2000
9	30.2500	39.9500	39.9500	30.2500
10	30.3000	40.0000	40.0000	30.3000

16 EXPLANATION OF CPU DATA COMMUNICATION

16.1. STAND-BY -> TALK, TALK -> STAND-BY
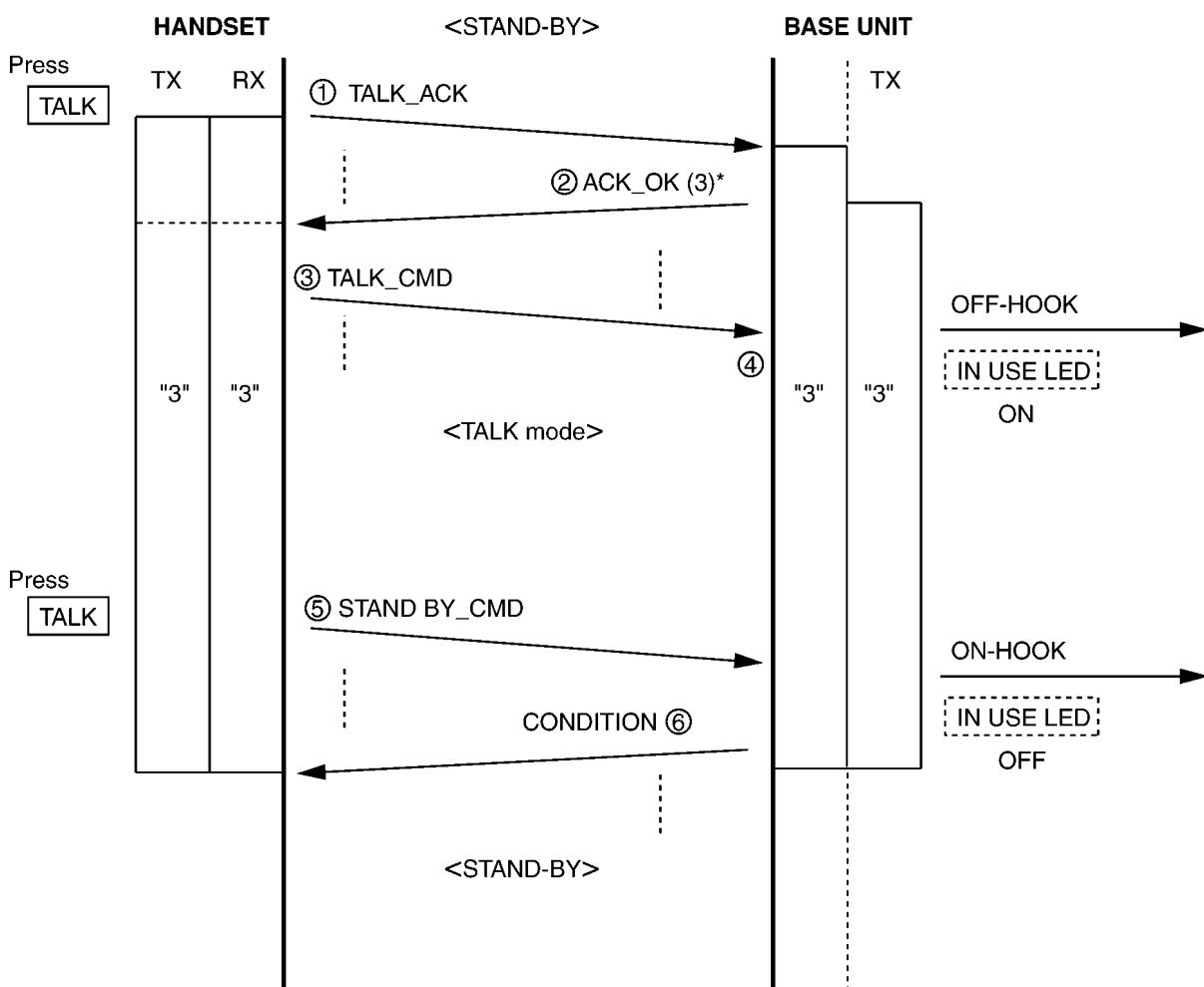
Press the TALK button

① The handset transmits TALK_ACK.
② Then base unit transmits ACK_OK including the channel number (Example: "3").
③ The handset transmits TALK_CMD.
④ The base unit goes to off-Hook mode.

Press the TALK button

⑤ The handset transmits STANDBY_CMD at the channel.
⑥ The base unit transmits CONDITION at the TALK channel.

*: The channel is changed if the noise interferes with the conversation.

16.2. Ringing
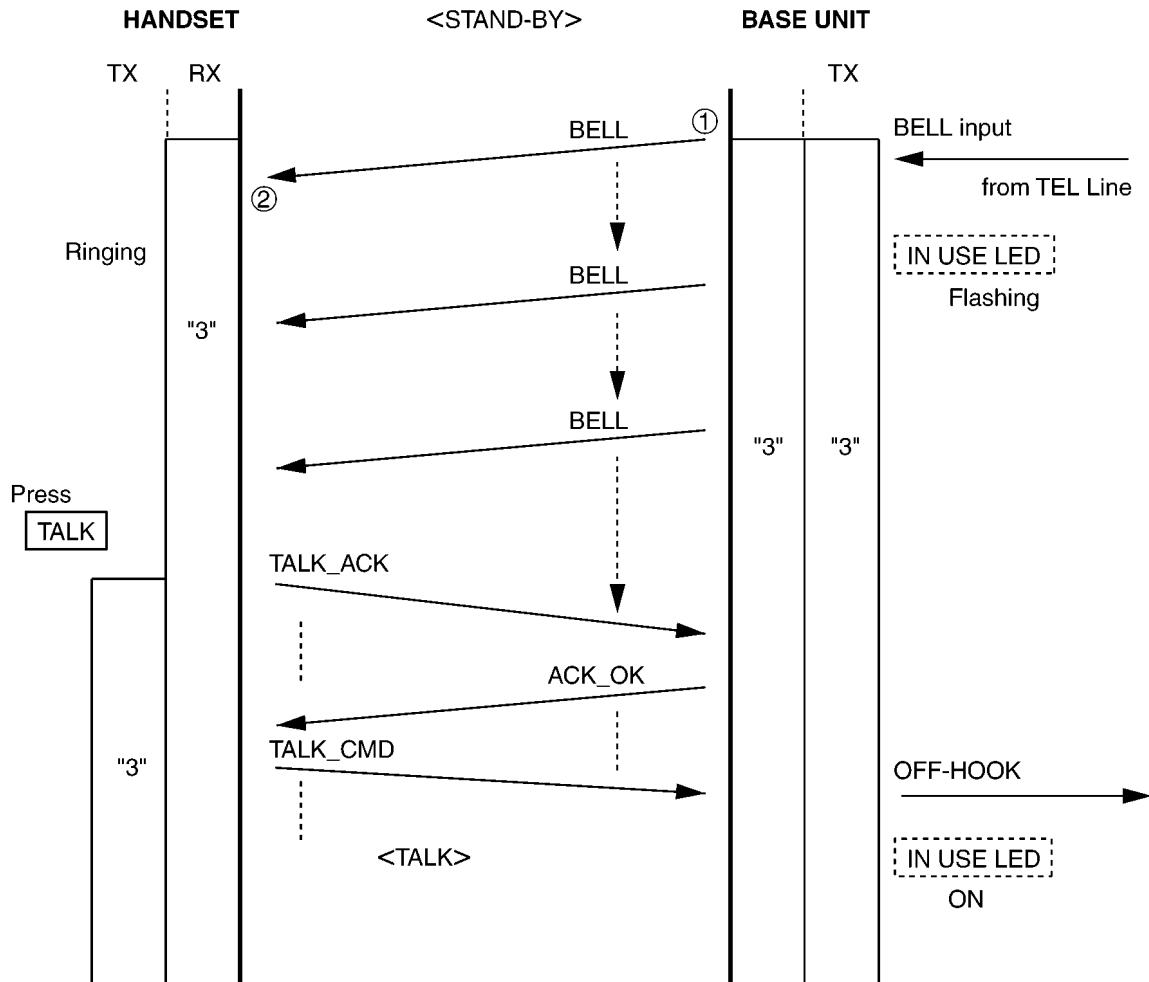
① When the bell signal is input, the base unit transmits BELL.
② The handset rings the bell on receiving BELL.

16.3. Changing the Channel

HANDSET   <TALK> or <INTERCOM>   **BASE UNIT**

Press the CH button.
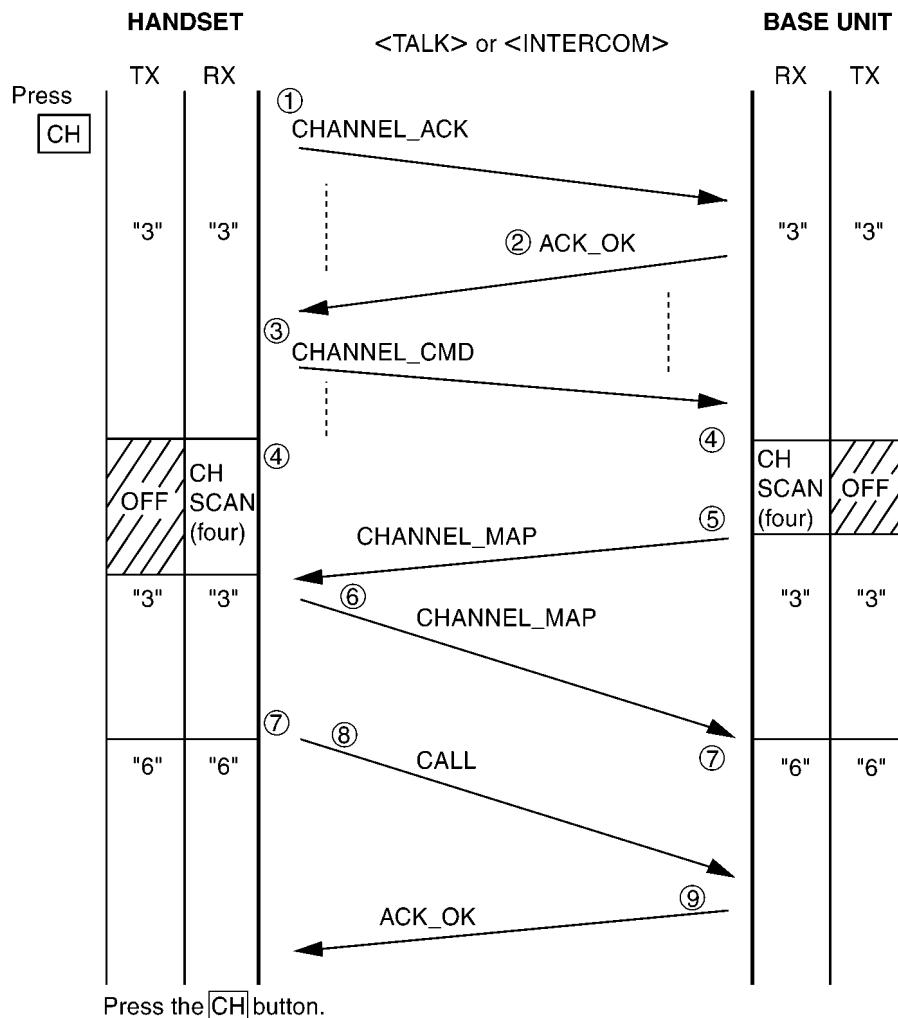
① The handset transmits CHANNEL_ACK.
② The base unit replies with ACK_OK.
③ Then handset transmits CHANNEL_CMD.
④ The handset and base unit turn off tx power and scan the channel map for next four channel.
⑤ The handset transmits CHANNEL_MAP.
⑥ The base unit transmits CHANNEL_MAP.
⑦ The handset and base unit moves to the "vacant channel". (Example: "6").
⑧ The base unit transmits CALL.
⑨ The handset transmits ACK_OK.

16.4. Ports for transmitting and receiving of data

Handset:

transmitting (TX) ... 36 Pin

receiving (RX) ... 4 Pin

Base Unit:

transmitting (TX) ... 17 Pin

receiving (RX) ... 10 Pin

16.5. Waveform of DATA used for cordless transmission and reception

The DATA which is transmitted from the Handset to the Base Unit is combination of DATA 0, DATA 1, PSEUD.

The DATA which is transmitted from the Base Unit to the Handset is combination of DATA 0, DATA 1, PSEUD.

16.5.1. Handset

Transmitting DATA Element Format

DATA 0

1800 µs   or   1800 µs

DATA 1

1800 µs   or   1800 µs

PSEUD 0

300 µs   or   300 µs

16.5.2. Base Unit

DATA 0

1800 µs   or   1800 µs

DATA 1

1800 µs   or   1800 µs

PSEUD 0

300 µs   or   300 µs
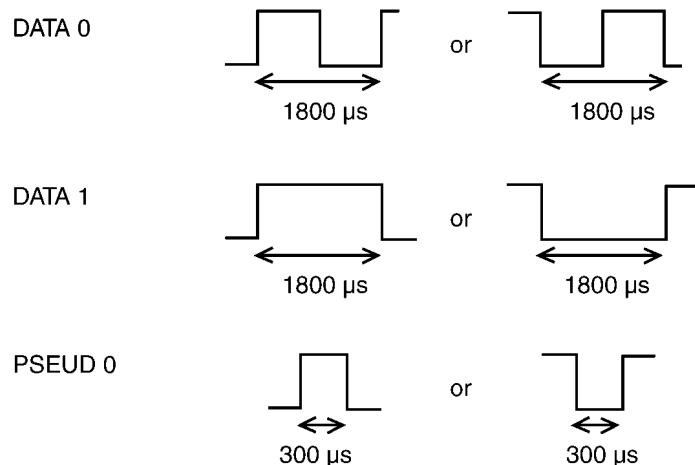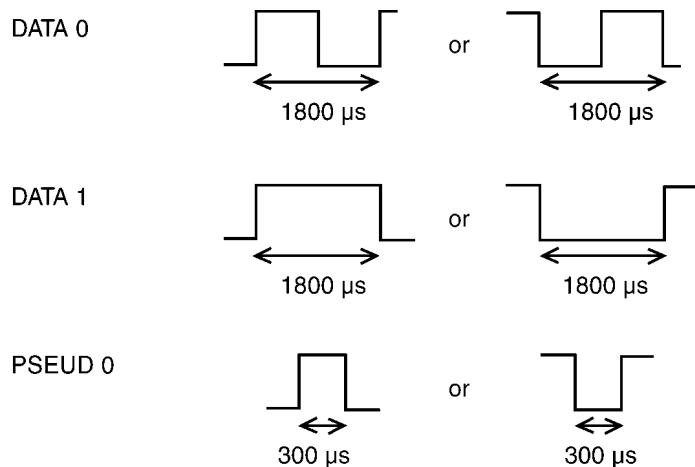
● For example (one of part of data)

0   1   PSEUD 0   1   1   0   1   0
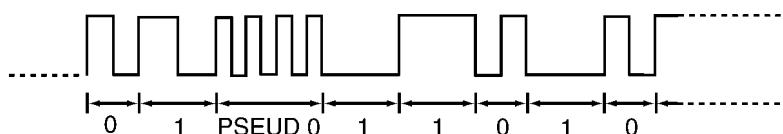
17 BLOCK DIAGRAM (BASE UNIT)
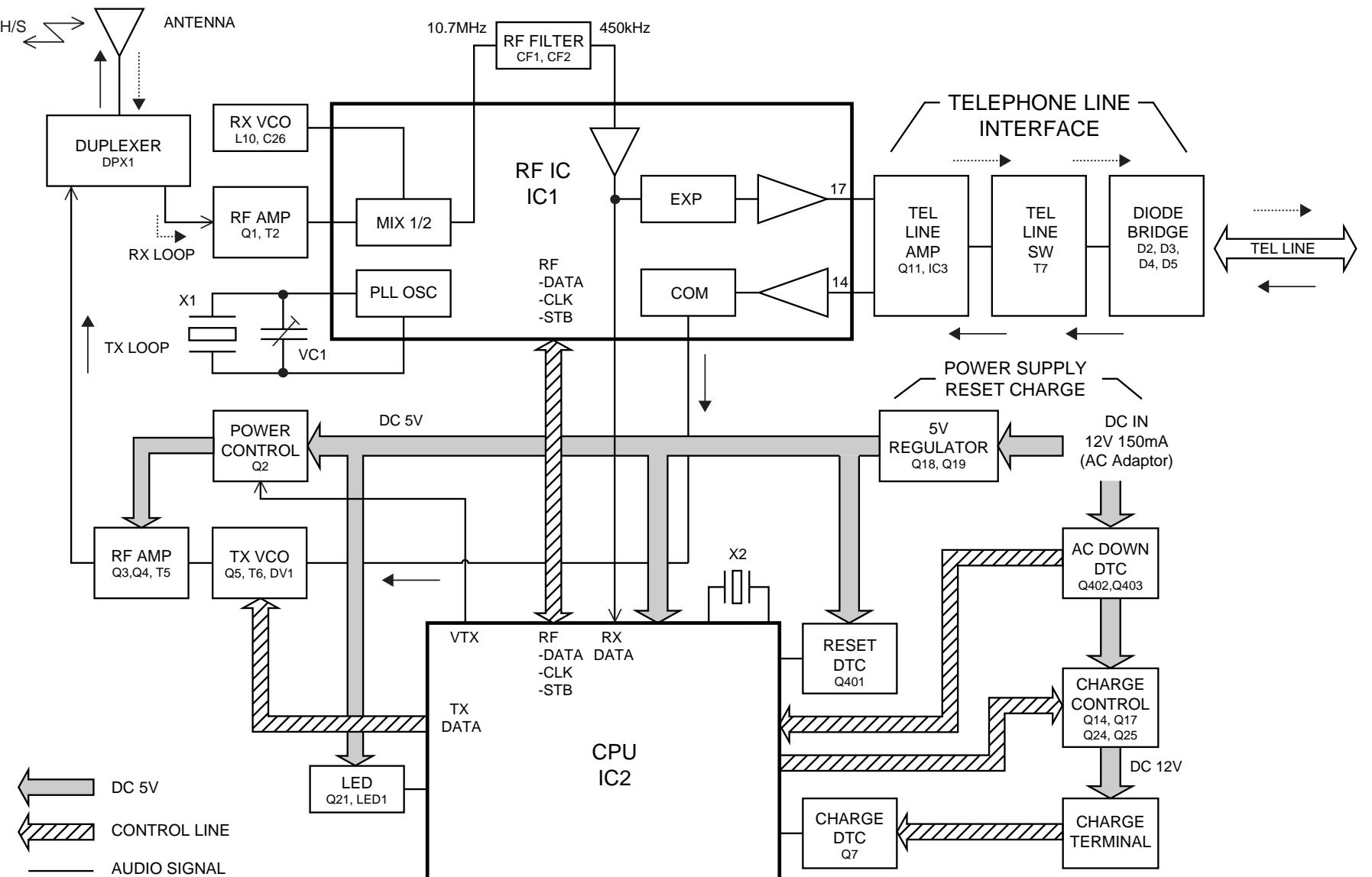
KX-TC2000NZB/W/F BLOCK DIAGRAM (BASE UNIT)

18 BLOCK DIAGRAM (HANDSET)

Base

ANTENNA

RF FILTER
CF1, CF2

DUPLEXER
DPX1

RX VCO
L6, C24

RF IC
IC1

RF AMP
Q1, T3

MIX 1/2

RX LOOP

EXP

SPEAKER
REC1

DC 3.9V

CONTROL LINE

AUDIO SIGNAL

PLL OSC

RF
-DATA
-CLK
-STB

COM

MIC
MC1

X1

VC1

TX LOOP

POWER
CONTROL
Q4

DC 3.9V

BATTERY
3.9V

RF AMP
Q5, T5
Q200

TX VCO
Q6, T6, DV1

X3

DIODE
BRIDGE
Q9

VTX

RF
-DATA
-CLK
-STB

RX
DATA

RESET
Q11

DIODE
BRIDGE
D1

CHARGE
TERMINAL

TX
DATA

CPU
IC2

CHARGE
DTC
IC2 PING37

LED
Q8, LED 1-4

BUZZER
Q7, BZ1
Q12

KEY BOARD

KX-TC2000NZB/W/F BLOCK DIAGRAM (HANDSET)

19 CIRCUIT OPERATION

19.1. Outline

Base unit consists of the following ICs as shown in BLOCK DIAGRAM.

- CPU:IC2
  - Controlling the whole system
  - Forming/analyzing all data signals (ACK, CMD signal etc.*)
  - All interfaces (ex: LED, KEY, SP, Mic, LCD, Detector Circuit (Charge/ Power Down)

    *Refer to **EXPLANATION OF CPU DATA COMMUNICATION** (P.34).
- RF IC:IC1
  - PLL Oscillator
  - Detection
  - Compress/ Expander
  - first/ second mixer
  - Amplifier for transmission and reception
- Additionally,
  - Power Supply Circuit
  - Reset Circuit
  - Charge Circuit
  - Telephone Line Interface Circuit

Handset consist of the following ICs as shown in BLOCK DIAGRAM.

- CPU: IC2
  - All data signals (forming/analyzing ACK or CMD signal*)
  - All interfaces (ex; LED, Key, Buzzer, Detector Circuit, Charge, Battery Low)
  - RAM for keeping the data (CH Number, ID Code, etc.)
- RF IC:IC1
  - PLL Oscillator
  - Detector
  - Compress/Expander
  - first, second mixer
  - Amplifier for transmission and reception

    *Refer to **EXPLANATION OF CPU DATA COMMUNICATION** (P.34).

19.2. Power Supply Circuit

The power supply to the CPU (Digital, Analog) and RF IC from AC Adaptor (+12V) is shown in the diagram below.

The base unit power supply is DC12V. The handset´s power is supplied from 3.6V battery (Nickel-Cadmium battery) which is installed in the handset.

Power supply for transmitter is turned on by a press of "Talk" key on the handset. During the stand-by mode, the unit stops transmitting but receives the signal.

Also during on-hook condition (the handset is placed on the base unit), backup power for memory of the last dialed number is supplied through the battery. The memory of this unit is not backed up by the current from the telephone line.

The base unit DC power supply is regulated by Q18, the CPU power is regulated by Q19. The Q401, Q403 detects AC Adaptor power failure and maintains the unit security code.
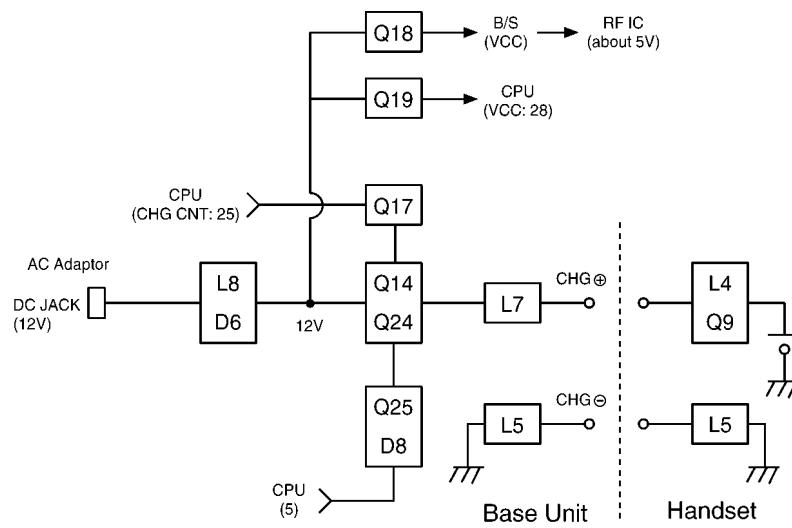
Fig. 1

19.3. Reset Circuit (Base Unit)

After power supply from AC adaptor, the below circuit is for making reset signal. Refer to the below waveform.
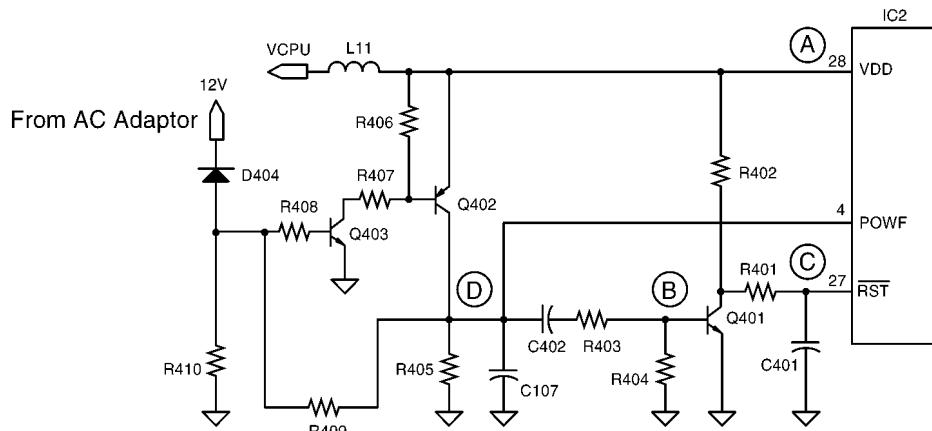
Fig. 2
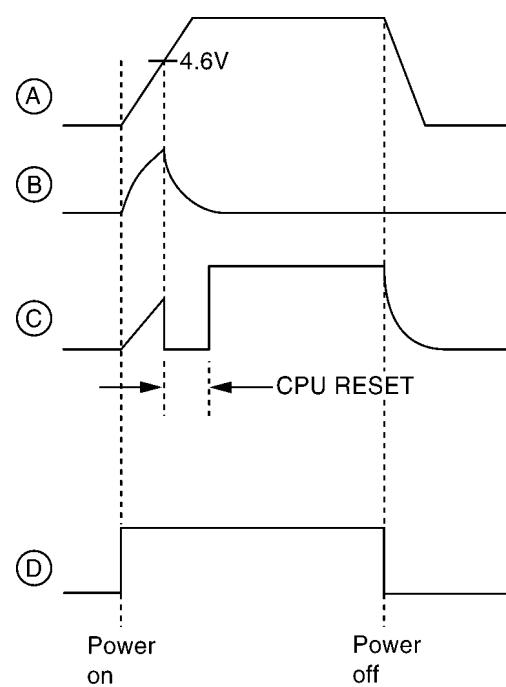
Fig. 3

19.4. Charge Circuit

Circuit Operation:

When charging the handset on the base unit, the charge current is as follows;

DC (JK2) → L8 → D6 → Q14 → Q24 → L7 → CHG+(Base) → [CHG+(Handset) → L4 → Q9 → BATT(1)....Battery....BATT(2) → L5 →

CHG-(Handset)] → CHG-(Base) → L5,

In this way, the CPU on both unit detects the fact that the battery is charged.

The charge current is controlled by switching Q24, Q25 of Base Unit. The battery is charged in normal mode for 15 hours and then in trickle mode.

19.5. Telephone Line Interface

Function:

- Bell signal detection
- ON/OFF hook and pulse dial circuit
- Side tone circuit

Bell signal detection and OFF HOOK circuit:

In the idle mode, Q103 is open to cut the DC loop current and decrease the ring load. When ring voltage appears at the Tip (T) and Ring (R) leads (When the telephone rings), the AC ring voltage is transferred as follows:

JK1 (3): T → L6 → R184 → R144 → IC3D (12,13 → 14) → C97 → R148 → Q20 → IC2 (24) [**BELL**]

JK1 (2): R → L4 → R183 → R152 →↑

When the CPU (DSP) detects a ring signal and press the TALK Key on the handset. Q6 turns on and then RY1 turns on, thus providing an off-hook condition (active DC current flow through the circuit) and the following signal flow is for the loop current.

T → R160 → L4 → D2 → RY1 → R107 → T7 → R116 → D5 → L6 → R161 → R [**OFF HOOK**]

ON HOOK Circuit:

Q6 is open, RY1 disconnected as to cut the DC loop current and to cut the voice signal. The unit is consequently in an on-hook condition.

Side Tone Circuit:

Basically this circuit prevents the TX signal from feeding back to RX signal.

As for this unit, TX signal feed back from Q11 is canceled by the cancellor circuit of AGC.

19.6. DTMF

The DTMF signal is generated by five outputs of IC2 (CPU) and output to telephone line through the filter of IC3A which is a lowpass filter as shown below.

The combination of five outputs "1", "0" makes 32 (=2✕5) level signals and makes smooth waveform after filter like a DTMF generator.

43
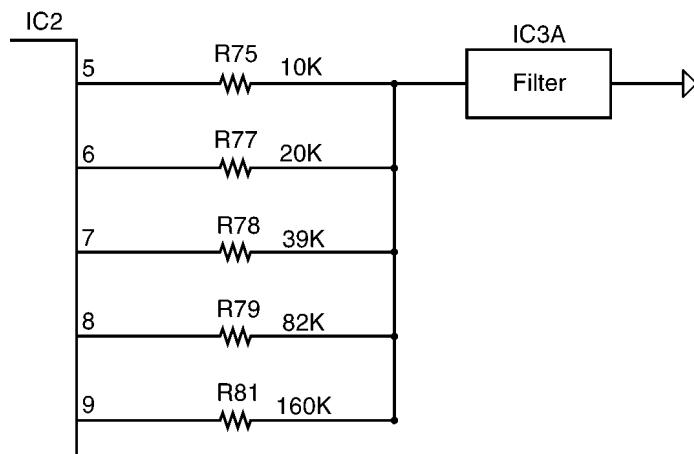
19.7. Transmitter/Receiver

Base Unit and Handset are mainly consists of RF(Radio Frequency) IC and CPU.

Base Unit and Handset transmit/receive voice signal and data signal through the antenna on carrier frequency.

Signal Pass :

*Refer to CDL TX/RX in **Signal Route** (P.46).

19.7.1. Base to Handset

Circuit Operation:

The voice signal input from the TEL LINE interface goes to RF IC as shown in

BLOCK DIAGRAM (BASE UNIT) (P.38).

In the talk mode (off-hook) condition, the telephone line voice signal passes through D2, D3, D4, D5, RY1 (Relay), R107 and T7.

The other party´s voice signal is coupled with T7 and amplified by Q11 and led to IC3-B (OP Amplifier device).

And the signal goes through the compressor of RF IC, it is output to transmitter circuit.

The signal of the data sent to the handset is applied in the anode of the variable capacitor diode (VARICAP : DV1).

The capacitor of VARICAP is changing in accordance with the voice signal from telephone line interface or TX DATA signal from CPU. Therefore, the carrier frequency which is generated by TXVCO will be changing, and Frequency modulated RF

signal is generated and amplified by RF AMP(Q3, Q4, T5). It pass through the Duplexer DPX1 and radiated from Antenna.

The signal is transmitted from the base unit and received by the handset antenna and amplified by RF amplifier (Q1) through DPX1 as shown in **BLOCK DIAGRAM (HANDSET)** (P.39). And then it is converted to 10.7 MHz and 455 KHz Intermediate frequency by RF IC and related components.

The demodulated audio signal is output from RF IC (DET OUT) and passed through "Expander" process to reduce noise, then voice signal amplified by "Receiver amplifier" is output to receiver (REC1).

The receiver loudness is adjustable using "LOUD" key on the handset. Q2 and Q3 control the volume. When CPU (VOL1) becomes low, the volume becomes "MID", while CPU (VOL1, 2) become low, the volume becomes "HIGH".

TX data (to Handset)

CPU (VTX) becomes low to turn on the transmission power transistor Q2, and CPU (TX-data) sends data signal. It is FM-modulated by TXVCO and driven by RF AMP, then transmitted to the handset.

19.7.2. Handset to Base

Circuit Operation:

The voice signal from the handset user is picked up by the microphone (MC1), voice signal passes through "Compressor" process to reduce noise as shown in **BLOCK DIAGRAM (HANDSET)** (P.39). And the voice is FM-modulated by VARICAP (DV1).

The carrier frequency is generated by TX VCO. The transmitter power transistor Q4 is turned on/off by CPU (VTX).

The carrier signal is amplified by RF AMP and sent to the handset duplexer and antenna.

The signal of 39MHz band (39.775~40.000MHz) which is input from ANT is filtered at DPX1 as shown in **BLOCK DIAGRAM (BASE UNIT)** (P.38), then it is input to RF IC.

The signal input to RF IC is converted through Mixer inside of RF IC, RF filter (CF1, CF2) and Expander.

The signal is transmitted from the handset and received by the base unit antenna and amplified by RF amplifier Q1, then it is converted to10.7 MHz and 450 KHz Intermediate by RF IC. The demodulated audio signal is output from RF IC (DET OUT) and passed through "Expander" process to reduce noise, then voice signal is led to LINE AMP. The signal is passed through TELEPHONE INTERFACE and Tel-line.

RX data (from Handset):

The data signal from handset (ex: Talk, ACK, COM) is also included in 39 MHz band same as the voice data. After second if filter, the data signal is made square shape by data limiting AMP of the RF IC. RX data is output to CPU (RX Data).

19.7.3. RF signal operation/control and PLL operation (RF UNIT)

Base unit radio frequency signal received by antenna passes through duplexer (DPX1).

RF signal is amplified by RF AMP. RF signal received from RF IC is mixed with RX local frequency at Mixer to generate 10.7 MHz wide band IF. The reference frequency is generated by X1 11.150 MHz crystal. VC1 is the reference frequency for adjustment. The 10.7 MHz is mixed with reference and 450KHz narrow band IF is generated. The demodulation audio signal is adjusted to the maximum at T1. RF IC is controlled by CPU (RF_STB, DATA, CLK). The RX local frequency is generated by RXVCO.

19.8. Signal Route

Each signal route is as follows.

SIGNAL ROUTE	IN ────signal────▶ ROUTE ────────────▶ OUT
CDL TX **(to Tel Line)**	**(HANDSET)** MIC - C45 - R30 - R29 - IC1 (14) - IC1 (11) - R25 - R26 - IC1 (10) - IC1 (9) - C49 - R41 - R45 - C53 - T6 - C57 - Q6 - C60 - Q5 - T5 - C201 - Q200 - C200- DPX1 - L1 - ANTENNA - To BASE UNIT **(BASE UNIT)** From HANDSET - ANTENNA - L1 - DPX1 - Q1 - T2 - C19 - IC1 (40) - IC1 (38) - CF1 - C7- IC1 (36) - IC1 (34) - CF2 - IC1 (32) - IC1 (27) - R4 - C28 - R21 - IC1 (15) - IC1 (17) - C32- R18 - Q11 - T7 - R116 ⌐ D3 - L4 - TIP : JK1 (2) └ D5 - L6 - RING : JK1 (3)

CDL RX
(from Tel Line)
	(BASE UNIT)
	     JK1 (2): TIP - L4 - D2
	JK1 (3): RING - L6 - D4 ─┴─ RY1 -R107 - T7 - R119 - C92 - R141 - C77 - C44 - R26 -
	IC1 (14) - IC1 (11) - R23 - R24 - IC1 (10) - IC1 (9) - C48 - R38 - R44 - C52 - T6 - C57 -
	Q5 - C56 - Q4 - C60 - Q3 - T5 - C46 - DPX1 - L1 - ANTENNA - to HANDSET
	
	(HANDSET)
	from BASE UNIT - ANTENNA - L1 - DPX1 - Q1 - T3 - C17 - IC1 (40) - IC1 (38) - CF1 -
	IC1 (36) - C6 - IC1 (34) - CF2 - IC1 (32) - IC1 (27) - R3 - C33 - R23 - IC1 (15) - IC1 (17) -
	C32 - R18 - C30 - R16 - IC1 (18) ⌐ IC1 (19) - REC1
	                             └ IC1 (20) - REC1

20 CIRCUIT OPERATION (HANDSET)

20.1. Reset Circuit (Handset)

The power of handset is supplied by battery.

Whenever the battery is recharged or inserted, the impulse at CHG+ becomes Reset signal through Q11, and sent to CPU.
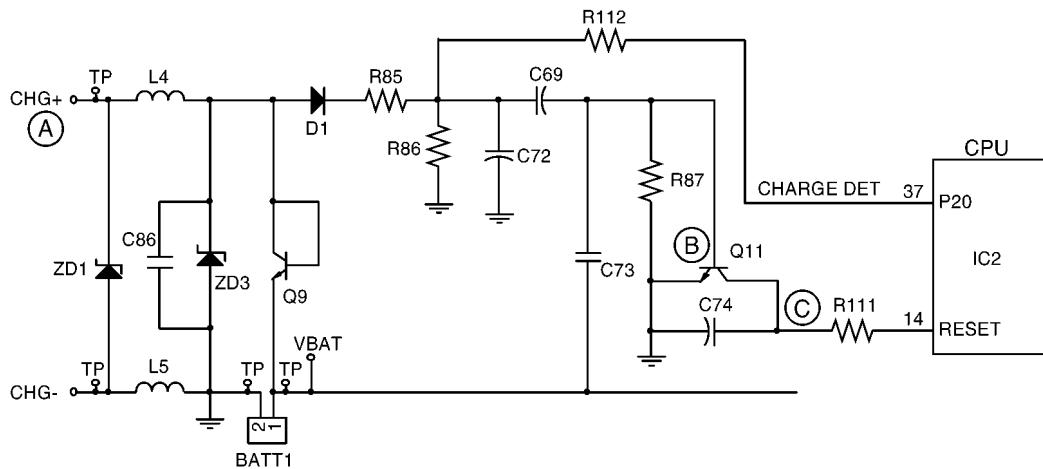
Fig. 4
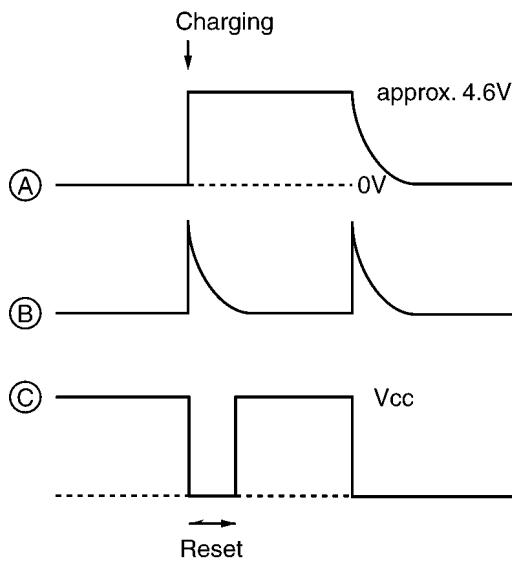
Fig. 5

20.2. Battery Low / Power Down Detector

Circuit Operation:

"Battery Low" and "Power Down" are detected by RF IC which check the voltage from battery. Shortly, every detected blocks are inside of RF IC. The detected voltage is as follows;

- Battery Low

Battery voltage : V(Batt) < 3.457V

The CPU detects this level and "Recharge battery" LED starts flashing.

- Power Down

Battery voltage : V(Batt) < 3.0V

The output of RF IC (P-DOWN) becomes low level, then CPU stops working to keep the data (CH number, ID Code, etc.)
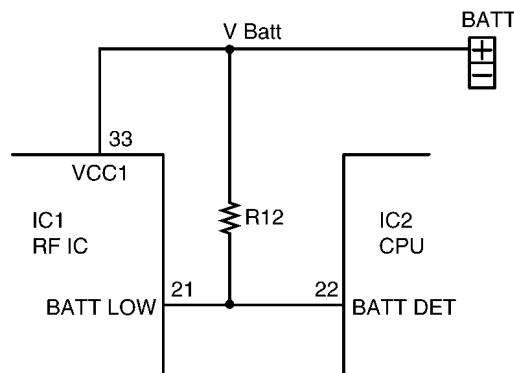
Fig. 6

21 CPU DATA (Base Unit)

21.1. IC2

Pin	Description	I/O	High	Hi-z	Low
1	NC	A.O	-	-	-
2	NC	A.I	-	-	-
3	NC	D.I	-	-	-
4	PWRDET	D.I	Active	-	Normal
5	DTMF4	D.O	Active	-	Normal
6	DTMF3	D.O	Active	-	Normal
7	DTMF2	D.O	Active	-	Normal
8	DTMF1	D.O	Active	-	Normal
9	DTMF0	D.O	Active	-	Normal
10	RXD	D.I	-	-	-
11	COUNT0	D.I	-	-	-
12	ASTB	D.O	Active	-	Normal
13	ADAT	D.O	-	-	Normal
14	NC	-	-	-	-
15	ACLK	D.O	-	-	Normal
16	PULSEMUTE	D.O	Active	-	Normal
17	TXD	D.O	Active	Normal	Active
18	CHGDET	D.I	Active	-	Normal
19	CNDET	D.I	Active	-	Normal
20	VTX	D.O	Normal	-	Active
21	HOOK	D.O	Active	-	Normal
22	PAGE	D.I	Normal	-	Active
23	COUNT1	D.I	-	-	-
24	RINGDET	D.I	-	-	-
25	CHARG-CNT	D.O	Normal	-	Active
26	LINELED	D.O	Normal	-	Active
27	RST	D.I	-	-	-
28	VDD	A.I	-	-	-

22 CPU DATA (Handset)

22.1. IC2

Pin	Description	I/O	High	Hi-z	Low
1	ADAT	D.O	-	-	Normal
2	ACLK	D.O		-	Normal
3	RXPWR	D.O	Normal	-	Active
4	RXD	D.I	-	-	-
5	BACKLED	D.O	Active	-	Normal
6	TALKLED	D.O	Normal	-	Active
7	LOWLED	D.O	Normal	-	Active
8	COL 3	D.I	Normal	-	Active
9	COL 2	D.I	Normal	-	Active
10	COL 1	D.I	Normal	-	Active
11	COL 0	D.I	Normal	-	Active
12	NC	D.O	Normal	-	-
13	NC	D.I	-	-	Normal
14	RESET	D.I	Normal	-	Reset
15	XIN	A.I	-	-	-
16	XOUT	A.O	-	-	-
17	GND	-	-	-	-
18	NC	-	-	-	-
19	OPTION 0	D.I	-	-	-
20	OPTION 1	D.I	-	-	-
21	OPTION 2	D.I	-	-	-
22	BATTDET	D.I	Active	-	Normal
23	CRDET	D.I	Active	-	Normal
24	NC	D.O	Normal	-	-
25	NC	D.O	Normal	-	-
26	NC	D.O	Normal	-	-
27	NC	D.O	Normal	-	-
28	NC	D.O	Normal	-	-
29	ROW 0	D.O	Normal	-	Active
30	ROW 1	D.O	Normal	-	Active
31	ROW 2	D.O	Normal	-	Active
32	ALERT	D.O	Normal	-	Active
33	ROW 3	D.O	Normal	-	Active
34	ROW 4	D.O	Normal	-	Active
35	ROW 5	D.O	Normal	-	Active
36	TXD	D.O	Active	Normal	Active
37	CHGDET	D.I	Active	-	Normal
38	XTIN	A.I	-	-	-
39	XTOUT	A.O	-	-	-
40	VDD	A.I	-	-	-
41	BUZCNTL	D.O	Active	-	Normal
42	VOL 1	D.O	Active	-	Normal
43	VOL 2	D.O	Active	-	Normal
44	RF-STB	D.O	Active	-	Normal

23 RF IC (Base Unit and Handset)

23.1. IC1

Pin	Description	I/O	Pin	Description	I/O
1	TX IN	A.I	25	FIL-IN	A.I
2	VCC3	A.I	26	FIL-OUT	A.O
3	LO1	-	27	DET OUT	A.O
4	LO2	-	28	QUAD	-
5	S-OUT	D.O	29	IF OUT	A.O
6	CLK	D.I	30	GND 2	-
7	DATA	D.I	31	DEC	-
8	STB	D.I	32	IF IN	A.I
9	FL-OUT	A.O	33	VCC1	A.I
10	FL-IN	A.I	34	2ND MIX OUT	A.O
11	COMP-OUT	A.O	35	N-REC	-
12	C-NF	-	36	2ND MIX IN	A.I
13	AF-OUT	A.O	37	E-REC	-
14	AF-IN	A.I	38	1ST MIX OUT	A.O
15	REF-IN	A.I	39	VREF	-
16	REF-OUT	A.O	40	1ST MIX IN	A.I
17	EXP-OUT	A.O	41	VCC2	A.O
18	REC-IN	A.I	42	VCO CONT	A.I
19	RO1	A.O	43	VCO1	-
20	RO2	A.O	44	VCO2	-
21	BAT. ALM	D.O	45	C-RECT	-
22	RSSI	A.O	46	RX CF	A.O
23	DATA O/P	A.O	47	TX CF	A.O
24	DATA I/P	A.I	48	PLL GND	-

24 HOW TO REPLACE FLAT PACKAGE IC

24.1. Preparation

● SOLDER

Sparkle Solder 115A-1, 115B-1 or Almit Solder KR-19, KR-19RMA

● Soldering iron

Recommended power consumption will be between 30 W to 40 W.

Temperature of Copper Rod 662 ± 50°F (350 ± 10°C)

(An expert may handle between 60 W to 80 W iron, but beginner might damage foil by overheating.)

● Flux

HI115 Specific gravity 0.863.

(Original flux will be replaced daily.)

24.2. Procedure

1. Temporary fix FLAT PACKAGE IC by soldering on two marked 2 pins.
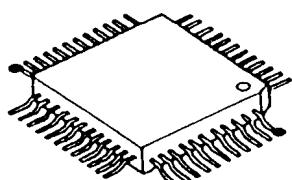
● – – – – – –Temporary soldering point.

*Most important matter is accurate setting of IC to the corresponding soldering foil.

2. Apply flux for all pins of FLAT PACKAGE IC.
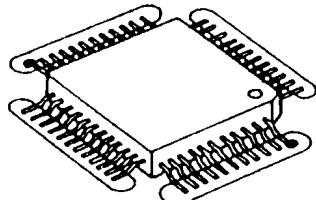
– – – – – Flux

3. Solder employing specified solder to direction of arrow, as sliding the soldering iron.

Soldering iron

Specified solder
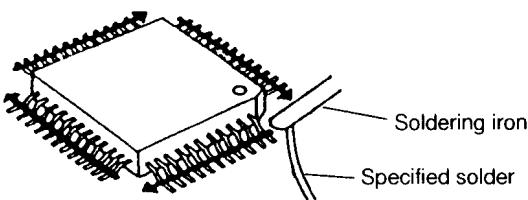
24.3. Modification Procedure of Bridge

1. Re-solder slightly on bridged portion.

2. Remove remained solder along pins employing soldering iron as shown in below figure.

bridge

52
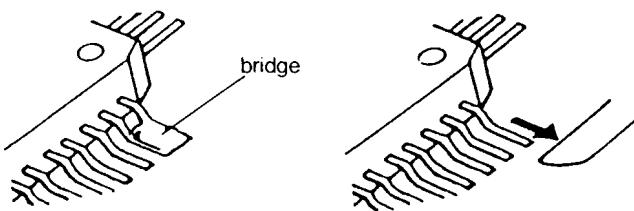
25 CABINET AND ELECTRICAL PARTS LOCATION (BASE UNIT)
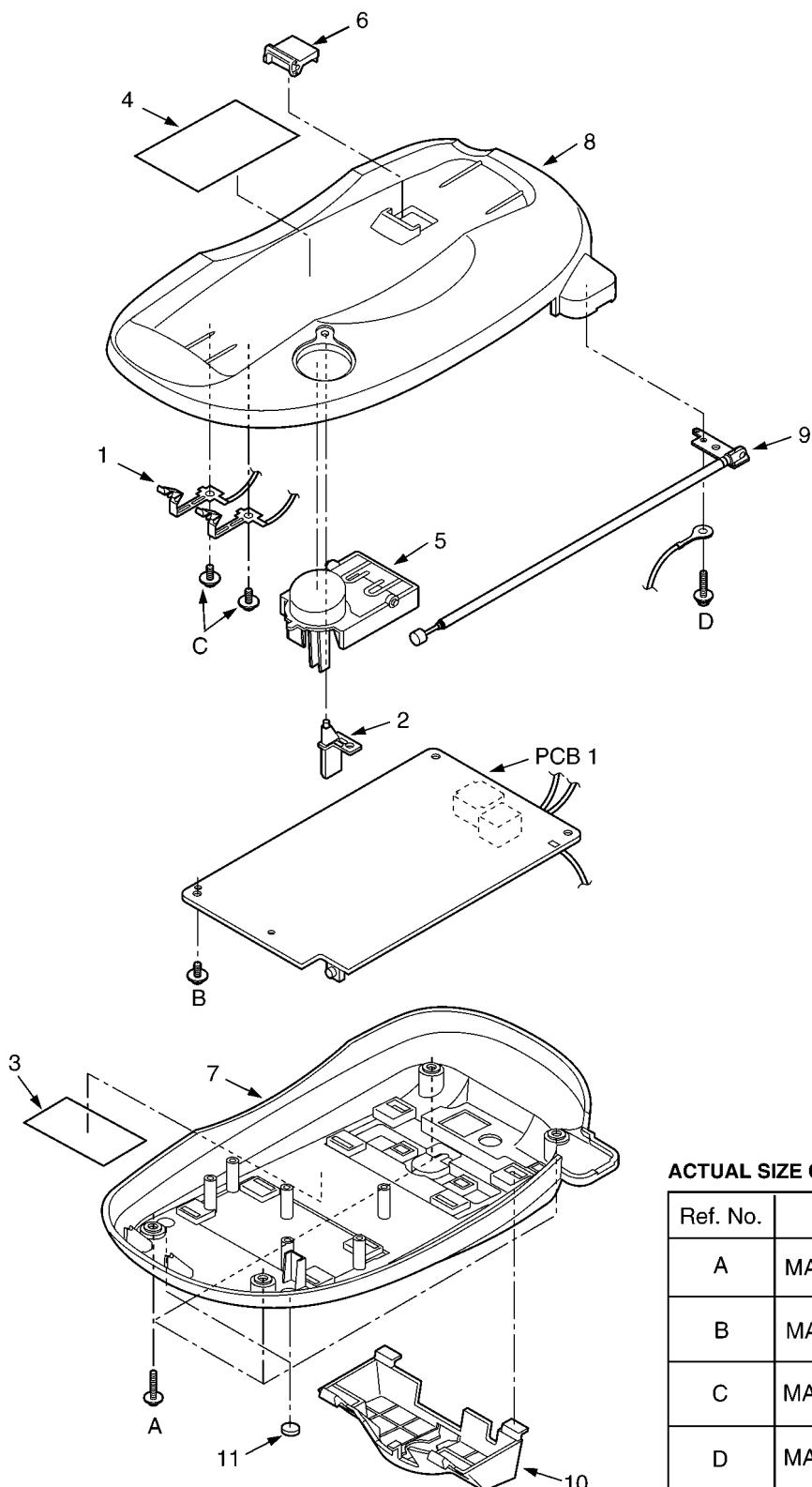
ACTUAL SIZE OF SCREWS

Ref. No.	Part No.	Screw
A	MAB0G261247	
B	MAB0G260640	
C	MAB0G260640	
D	MAB0E261244	

26 CABINET AND ELECTRICAL PARTS LOCATION (HANDET)
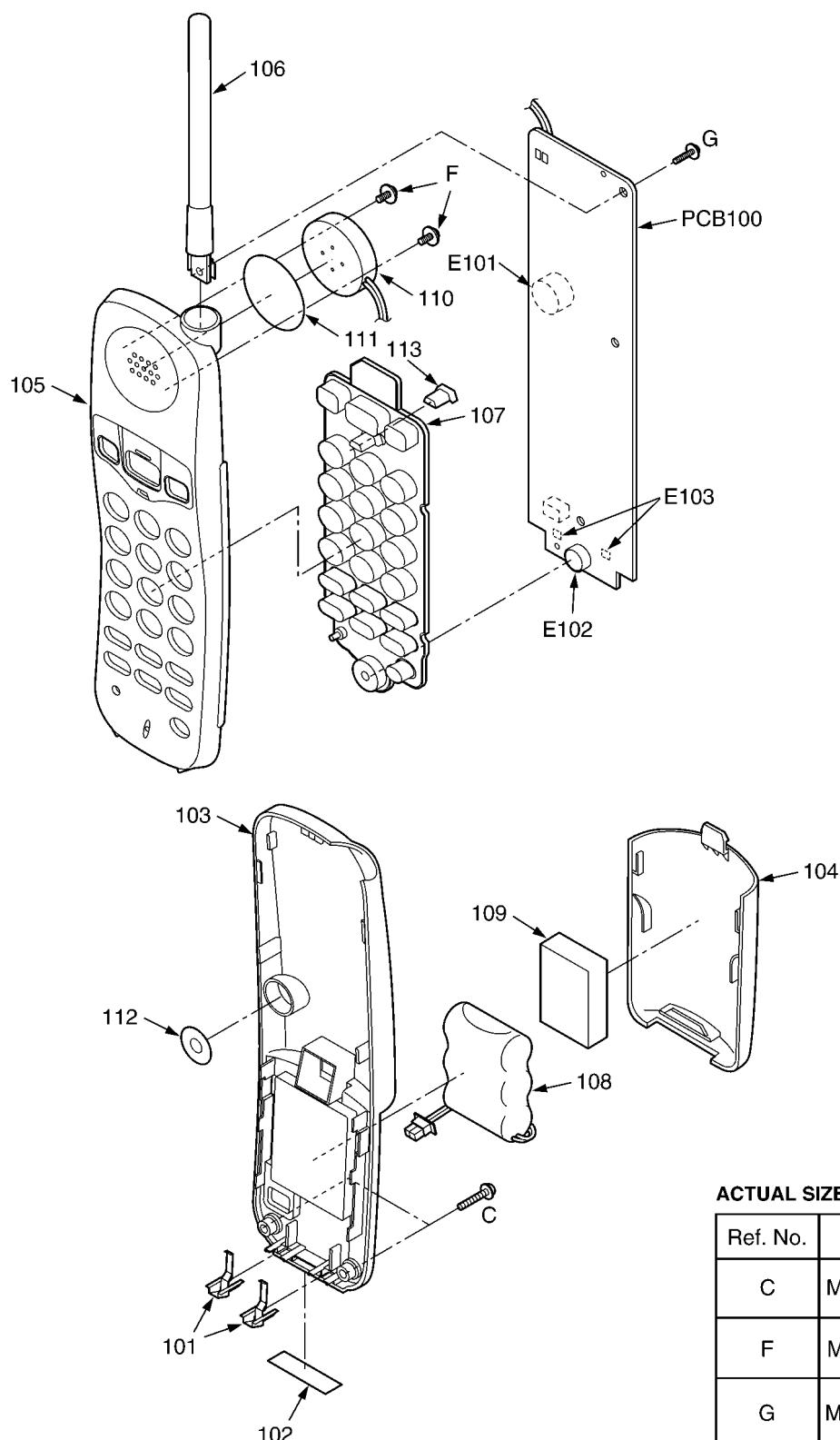
ACTUAL SIZE OF SCREWS

Ref. No.	Part No.	Screw
C	MAB0G261247	
F	MAB0G260640	
G	MAB0E261244	

27 ACCESSORIES AND PACKING MATERIALS
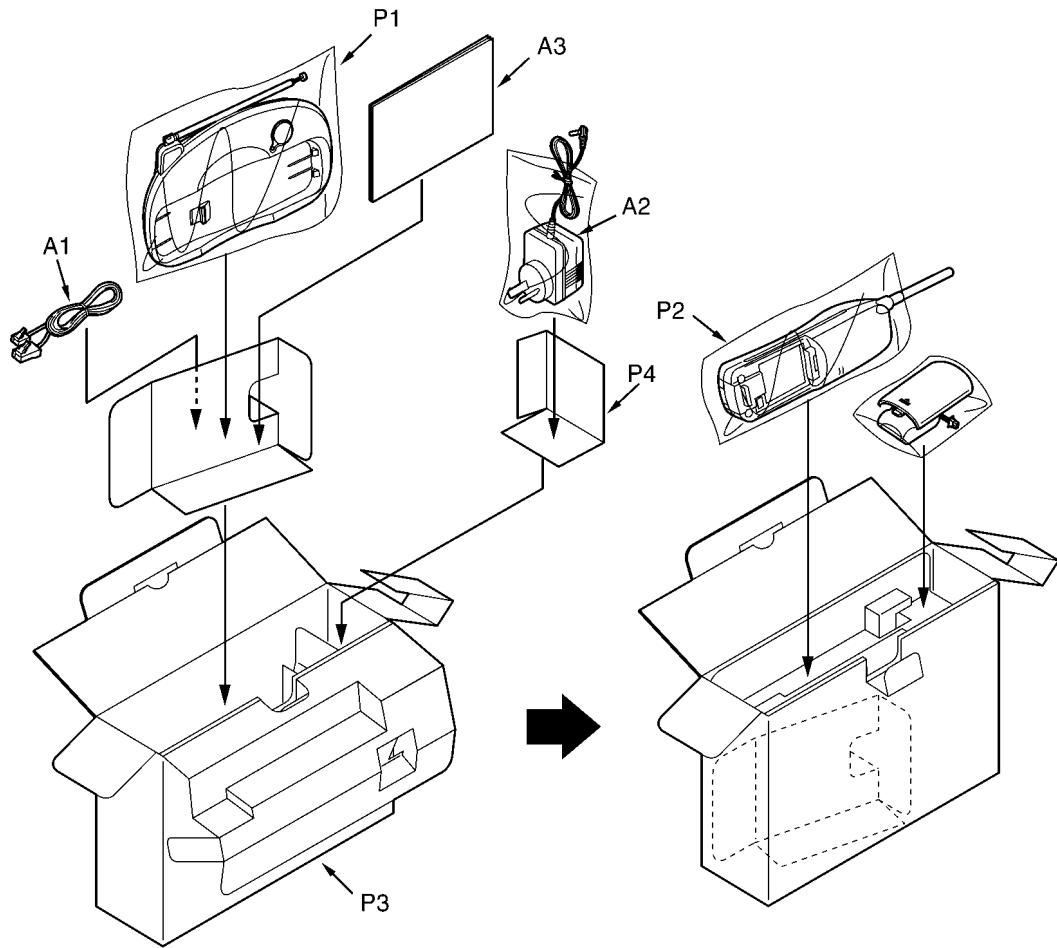
28 REPLACEMENT PARTS LIST

Note:

1. RTL (Retention Time Limited)

   The marking (RTL) indicates that the Retention Time is limited for this item.

   After the discontinuation of this assembly in production, the item will continue to be available for a specific period of time. The retention period of availability depends on the type of assembly and the laws governing parts and product retention.

   At the end of this period, the assembly will no longer be available.

2. Important safety notice

   Components identified by the ⚠ mark indicates special characteristics important for safety. When replacing any of these components, only use specified manufacture´s parts.

3. The S mark indicates service standard parts and may differ from production parts.

4. RESISTORS & CAPACITORS

   Unless otherwise specified;

   All resistors are in ohms (Ω) K=1000Ω, M=1000kΩ

   All capacitors are in MICRO FARADS (µF) P=µµF

   *Type & Wattage of Resistor

Type

ERC:Solid	ERX:Metal Film	PQ4R:Carbon
ERD:Carbon	ERG:Metal Oxide	ERS:Fusible Resistor
PQRD:Carbon	ER0:Metal Film	ERF:Cement Resistor

Wattage

10,16:1/8W	14,25:1/4W	12:1/2W	1:1W	2:2W	3:3W

*Type & Voltage of Capacitor

Type

ECFD:Semi-Conductor	ECCD,ECKD,ECBT,PQCBC : Ceramic
ECQS:Styrol	ECQE,ECQV,ECQG : Polyester
PQCUV:Chip	ECEA,ECSZ : Electrolytic
ECQMS:Mica	ECQP : Polypropylene

Voltage

ECQ Type	ECQG ECQV Type	ECSZ Type	Others		
1H: 50V	05: 50V	0F:3.15V	0J :6.3V	1V :35V
2A:100V	1:100V	1A:10V	1A :10V	50,1H:50V
2E:250V	2:200V	1V:35V	1C :16V	1J :63V
2H:500V		0J:6.3V	1E,25:25V	2A :100V

28.1. Base Unit

28.1.1. CABINET AND ELECTRICAL PARTS

Ref. No.	Part No.	Part Name & Description	Remarks
1	PQJT10180Z	CHARGE TERMINAL	
2	PQHR10998Z	LED LENS	
3	PQGT16253Z	NAME PLATE (for KX-TC2000NZB)	
3	PQGT16257Z	NAME PLATE (for KX-TC2000NZF)	
3	PQGT16255Z	NAME PLATE (for KX-TC2000NZW)	
4	PQQT22294Z	CHARGE LABEL	
5	PQBC10389Z1	LOCATOR BUTTON (for KX-TC2000NZB)	

Ref. No.	Part No.	Part Name & Description	Remarks
5	PQBC10389Y2	LOCATOR BUTTON (for KX-TC2000NZF)	
5	PQBC10389Z3	LOCATOR BUTTON (for KX-TC2000NZW)	
6	PQKE10335Z1	HOOK LEVER (for KX-TC2000NZB)	
6	PQKE10335Z2	HOOK LEVER (for KX-TC2000NZF)	
6	PQKE10335Z5	HOOK LEVER (for KX-TC2000NZW)	
7	PQKF10597Z1	LOWER CABINET (for KX-TC2000NZB/F)	
7	PQKF10597Z3	LOWER CABINET (for KX-TC2000NZW)	
8	PQKM10607X1	UPPER CABINET (for KX-TC2000NZB)	
8	PQKM10607W3	UPPER CABINET (for KX-TC2000NZF)	
8	PQKM10607X4	UPPER CABINET (for KX-TC2000NZW)	
9	PQSA10105Y	ANTENNA	
10	PQKL10056Z1	WALL MOUNT ADAPTOR (for KX-TC2000NZB/F)	
10	PQKL10056Z3	WALL MOUNT ADAPTOR (for KX-TC2000NZW)	
11	LCBT9300013	FOOT RUBBER	

28.1.2. MAIN P.C.BOARD PARTS

Ref. No.	Part No.	Part Name & Description	Remarks
PCB1	PQWPC2000ALH	MAIN P.C.BOARD ASS´Y (RTL)	
		(ICS)	
IC1	SA133122409	IC	
IC2	SA138740A11	IC	
IC3	SA1S0032402	IC	
IC5	AB1L0081715	IC	
		(TRANSISTORS)	
Q1	BB230024104	TRANSISTOR(SI)	
Q2	SB0I0390601	TRANSISTOR(SI)	
Q3	SB1D0390401	TRANSISTOR(SI)	
Q4	SB1D0390401	TRANSISTOR(SI)	
Q5	SB1D0390401	TRANSISTOR(SI)	
Q6	SB1I0390408	TRANSISTOR(SI)	
Q7	SB1I0390408	TRANSISTOR(SI)	
Q10	BB010009408	TRANSISTOR(SI)	
Q11	SB1I0390408	TRANSISTOR(SI)	
Q14	SB0I0390601	TRANSISTOR(SI)	
Q17	SB1I0390408	TRANSISTOR(SI)	
Q18	BB1M0390401	TRANSISTOR(SI)	
Q19	BB1M0390401	TRANSISTOR(SI)	
Q20	SB1I0390408	TRANSISTOR(SI)	
Q21	SB1I0390408	TRANSISTOR(SI)	
Q24	BB1M0390401	TRANSISTOR(SI)	
Q25	SB1I0390408	TRANSISTOR(SI)	
Q401	SB1I0390408	TRANSISTOR(SI)	
Q402	SB0I0390601	TRANSISTOR(SI)	
Q403	SB1I0390408	TRANSISTOR(SI)	
		(DIODES)	
D1	SC1GM414809	DIODE(SI)	
D2	BC2W0400401	DIODE(SI)	
D3	BC2W0400401	DIODE(SI)	
D4	BC2W0400401	DIODE(SI)	
D5	BC2W0400401	DIODE(SI)	
D7	VA02700A401	DIODE(SI)	
D8	SC1GM414809	DIODE(SI)	
D11	SC1GM414809	DIODE(SI)	
DV1	BC6K0025101	DIODE(SI)	
ZD1	BC050474801	DIODE(SI)	
ZD2	BC050474801	DIODE(SI)	
ZD3	SC4555C4V71	DIODE(SI)	
ZD4	BC4579C8V21	DIODE(SI)	
ZD5	SC4555C4V71	DIODE(SI)	
ZD8	BC4579C5V65	DIODE(SI)	
ZD9	BC4579C5V65	DIODE(SI)	
ZD10	SC4555C1506	DIODE(SI)	
ZD11	SV110201203	DIODE(SI)	
ZD12	SC4555C1506	DIODE(SI)	

Ref. No.	Part No.	Part Name & Description	Remarks		Ref. No.	Part No.	Part Name & Description	Remarks
ZD404	BC4579C7V50	DIODE(SI)			R53	ERJ3GEYJ153	15K	
		(LED)			R54	ERJ3GEYJ153	15K	
LED1	SC5E0192115	LED			R55	ERJ3GEYJ681	680	
		(COILS)			R56	ERJ3GEYJ222	2.2K	
L1	PQLQZK3R3J	COIL			R57	ERJ3GEYJ224	220K	
L3	PQLQZM120J	COIL			R58	ERJ3GEYJ221	220	
L4	PQLQZK120J	COIL			R59	ERJ3GEYJ104	100K	
L5	PQLQZK120J	COIL			R60	ERJ3GEYJ223	22K	
L6	PQLQZK120J	COIL			R62	ERJ3GEYJ104	100K	
L7	PQLQZK120J	COIL			R64	ERDS2TJ103	10K	
L10	PQLQZK1R2J	COIL			R68	ERJ3GEYJ104	100K	
L11	PQLQZM120J	COIL			R74	ERJ3GEY0R00	0	
DPX1	BDFL0083004	COIL			R75	ERJ3GEYJ103	10K	
		(JACKS)			R77	ERJ3GEYJ203	20K	
JK1	DC72P120018	JACK			R78	ERJ3GEYJ393	39K	
JK2	DC71P120023	JACK			R79	ERJ3GEYJ823	82K	
		(CERAMIC FILTERS)			R80	ERJ3GEYJ222	2.2K	
CF1	BDFA107MA07	CERAMIC FILTER			R81	ERJ3GEYJ164	160K	
CF2	BDFJ0450E08	CERAMIC FILTER			R82	ERJ3GEYJ103	10K	
		(CRYSTAL OSCILLATORS)			R83	ERJ3GEYJ103	10K	
X1	BD1H1115002	CRYSTAL OSCILLATOR			R84	ERJ3GEYJ103	10K	
X2	BD5H0795210	CRYSTAL OSCILLATOR			R85	ERJ3GEYJ103	10K	
		(TRANSFORMERS)			R86	ERJ3GEYJ473	47K	
T1	CLIP1200053	TRANSFORMER			R87	ERJ3GEYJ472	4.7K	
T2	CLIP1200100	TRANSFORMER			R88	ERJ3GEYJ103	10K	
T5	CLIP1200096	TRANSFORMER			R89	ERJ3GEYJ103	10K	
T6	CLIP1200142	TRANSFORMER			R90	ERJ3GEYJ274	270K	
T7	DG0P1200035	TRANSFORMER			R94	ERJ3GEYJ104	100K	
		(VARISTOR)			R95	ERJ3GEYJ392	3.9K	
ZNR1	VA107D271K1	VARISTOR			R96	ERJ3GEYJ334	330K	
		(RESISTORS)			R97	ERJ3GEYJ102	1K	
R1	ERJ3GEYJ470	47			R100	ERJ3GEYJ222	2.2K	
R2	ERJ3GEYJ331	330			R103	ERJ3GEYJ223	22K	
R3	ERJ3GEYJ153	15K			R104	ERJ3GEYJ472	4.7K	
R4	ERJ3GEYJ822	8.2K			R105	ERJ3GEYJ562	5.6K	
R5	ERJ3GEYJ103	10K			R106	ERDS2TJ220	22	
R6	ERJ3GEYJ103	10K			R107	ERJ3GEYJ241	240	
R7	ERJ3GEYJ334	330K			R108	ERJ3GEYJ472	4.7K	
R8	ERJ3GEYJ103	10K			R109	ERJ3GEYJ334	330K	
R10	ERJ3GEYJ393	39K			R110	ERJ3GEYJ104	100K	
R12	ERJ3GEYJ101	100			R111	ERJ3GEYJ471	470	
R13	ERJ3GEYJ623	62K			R112	ERJ3GEYJ102	1K	
R14	ERJ3GEYJ103	10K			R113	CQ52033RT27	33	
R15	ERJ3GEYJ562	5.6K			R114	ERJ3GEYJ223	22K	
R16	ERJ3GEYJ153	15K			R115	ERJ3GEYJ563	56K	
R18	ERJ3GEYJ222	2.2K			R116	ERJ3GEY0R00	0	
R19	ERJ3GEYJ563	56K			R118	ERDS1TJ121	120	
R20	ERJ3GEYJ184	180K			R119	ERJ3GEYJ823	82K	
R21	ERJ3GEYJ273	27K			R120	ERJ3GEY0R00	0	
R22	ERJ3GEYJ472	4.7K			R122	ERJ3GEYJ361	360	
R23	ERJ3GEYJ104	100K			R123	ERJ3GEYJ123	12K	
R24	ERJ3GEYJ103	10K			R126	ERJ3GEYJ201	200	
R25	ERJ3GEYJ683	68K			R129	ERJ3GEYJ622	6.2K	
R26	ERJ3GEYJ154	150K			R131	ERJ3GEYJ104	100K	
R30	ERJ3GEYJ104	100K			R132	ERJ3GEYJ222	2.2K	
R31	ERJ3GEYJ473	47K			R133	ERJ3GEYJ390	39	
R32	ERJ3GEYJ105	1M			R141	ERJ3GEYJ512	5.1K	
R33	ERJ3GEY0R00	0			R142	ERDS2TJ220	22	
R35	ERJ3GEYJ101	100			R143	ERJ3GEYJ514	510K	
R36	ERJ3GEYJ224	220K			R144	ERDS2TJ106	10M	
R37	ERJ3GEYJ101	100			R145	ERJ3GEYJ102	1K	
R38	ERJ3GEYJ104	100K			R146	ERJ3GEYJ153	15K	
R40	ERJ3GEYJ223	22K			R148	ERJ3GEYJ103	10K	
R41	ERJ3GEYJ473	47K			R149	ERJ3GEYJ182	1.8K	
R42	ERJ3GEYJ103	10K			R150	ERJ3GEYJ514	510K	
R43	ERJ3GEYJ103	10K			R152	ERDS2TJ106	10M	
R44	ERJ3GEYJ104	100K			R153	ERJ3GEYJ105	1M	
R45	ERJ3GEYJ474	470K			R154	ERJ3GEYJ470	47	
R46	ERJ3GEYJ222	2.2K			R155	ERJ3GEYJ470	47	
R48	ERJ3GEYJ223	22K			R156	ERJ3GEYJ470	47	
R49	ERJ3GEYJ753	75K			R159	ERJ3GEYJ104	100K	
R50	ERJ3GEYJ822	8.2K			R160	ERJ6GEY0R00	0	
R51	ERJ3GEYJ362	3.6K			R161	ERJ6GEY0R00	0	

Ref. No.	Part No.	Part Name & Description	Remarks
R166	ERJ3GEYJ470	47	
R167	ERJ3GEYJ103	10K	
R170	ERJ3GEYJ102	1K	
R172	ERDS2TJ223	22K	
R173	ERDS2TJ102	1K	
R174	ERDS2TJ102	1K	
R180	ERJ3GEYJ563	56K	
R181	ERJ3GEYJ331	330	
R183	ERJ6GEYJ106	10M	
R184	ERDS2TJ106	10M	
R185	ERJ3GEYJ104	100K	
R195	ERDS2TJ472	4.7K	
R197	ERJ3GEYJ223	22K	
R198	ERJ3GEY0R00	0	
R201	ERJ3GEYJ823	82K	
R202	ERJ3GEYJ132	1.3K	
R203	ERJ3GEYJ364	360K	
R401	ERJ3GEYJ102	1K	
R402	ERJ3GEYJ104	100K	
R403	ERJ3GEYJ104	100K	
R404	ERJ3GEYJ104	100K	
R405	ERJ3GEYJ104	100K	
R406	ERJ3GEYJ104	100K	
R407	ERJ3GEYJ472	4.7K	
R408	ERJ3GEYJ103	10K	
R409	ERJ3GEYJ824	820K	
R410	ERJ3GEYJ103	10K	
		(CAPACITORS)	
C1	ECEA1AKA470	47	
C2	ECUV1E104ZFV	0.1	S
C4	ECUV1H103KBV	0.01	
C6	ECUV1E104ZFV	0.1	S
C7	ECUV1H102KBV	0.001	
C8	ECUV1E104ZFV	0.1	S
C9	ECUV1H471JCV	470P	S
C10	ECUV1H471JCV	470P	S
C11	ECUV1H473MDV	0.047	S
C12	ECUV1H103KBV	0.01	
C15	ECEA1HKA2R2	2.2	
C16	ECUV1H270JCV	27P	
C17	ECEA1CKA100	10	
C18	ECUV1H473MDV	0.047	S
C19	ECUV1H102KBV	0.001	
C20	ECEA1HKA2R2	2.2	
C22	ECUV1H103KBV	0.01	
C23	ECUV1H103KBV	0.01	
C24	ECUV1E223ZFV	0.022	
C25	ECUV1H472KBV	0.0047	
C26	ECUV1H070CCV	7P	
C27	ECUV1H103KBV	0.01	
C28	ECUV1C104KBV	0.1	
C29	ECUV1E104ZFV	0.1	S
C30	ECEA1HKA2R2	2.2	
C31	ECUV1H103KBV	0.01	
C32	ECEA1HKA2R2	2.2	
C33	ECUV1H101JCV	100P	
C34	ECUV1H471JCV	470P	S
C35	ECUV1H180JCV	18P	
C36	ECUV1H101JCV	100P	
C37	ECUV1H151JCV	150P	
C38	ECEA1HKS010	1	S
C39	ECUV1H103KBV	0.01	
C40	ECUV1H270JCV	27P	
C42	ECEA1HKA2R2	2.2	
C43	ECUV1E104ZFV	0.1	S
C44	ECUV1A105ZFV	1	
C45	ECUV1H682KBV	0.0068	
C46	ECUV1H102KBV	0.001	
C47	ECUV1H103KBV	0.01	
C48	ECUV1H223KBV	0.022	S
C49	ECUV1H103KBV	0.01	
C50	ECEA1CKA220	22	
C51	ECUV1H103KBV	0.01	

Ref. No.	Part No.	Part Name & Description	Remarks
C52	ECUV1H223KBV	0.022	S
C53	ECUV1H120JCV	12P	
C54	ECUV1H020CCV	2P	
C55	ECUV1H103KBV	0.01	
C56	ECUV1H050CCV	5P	
C57	ECUV1H390JCV	39P	
C58	ECUV1H682KBV	0.0068	
C59	ECUV1H390JCV	39P	
C60	ECUV1H270JCV	27P	
C61	ECUV1E104ZFV	0.1	S
C62	ECUV1H390JCV	39P	
C63	ECUV1H103KBV	0.01	
C64	ECUV1E104ZFV	0.1	S
C65	ECUV1H220JCV	22P	
C66	ECEA0JKA102	1000	
C67	ECUV1H220JCV	22P	
C69	ECUV1H271KBV	270P	
C70	ECUV1H223KBV	0.022	S
C72	ECUV1H223KBV	0.022	S
C73	ECUV1E104ZFV	0.1	S
C74	ECUV1E104ZFV	0.1	S
C75	ECUV1H223KBV	0.022	S
C76	CATZ681KC68	680P	
C77	ECUV1H101JCV	100P	
C78	ECEA1AKA471	470	
C79	ECUV1E104ZFV	0.1	S
C80	CATZ681KC68	680P	
C82	ECUV1E104ZFV	0.1	S
C85	ECUV1C224KBV	0.22	
C90	ECUV1C474KBV	0.47	
C92	ECUV1E104ZFV	0.1	S
C93	ECUV1H562KBV	0.0056	
C94	ECEA1AKA101	100	
C95	ECEA1EKA471	470	
C96	ECUV1H103KBV	0.01	
C97	ECEA1HKA4R7	4.7	
C98	ECEA1CKA220	22	
C99	ECUV1H103KBV	0.01	
C101	ECUV1H562KBV	0.0056	
C102	ECEA1EKA221	220	
C103	ECEA1AKA470	47	
C104	ECUV1E104ZFV	0.1	
C105	ECEA1AKA101	100	
C106	ECUV1A105ZFV	1	
C107	ECUV1E104ZFV	0.1	S
C108	ECUV1E104ZFV	0.1	S
C109	ECUV1H682KBV	0.0068	
C110	ERJ3GEYJ102	1K	
C122	ECUV1A154KBV	0.15	
C123	ECUV1A474KBV	0.47	
C124	ECUV1C224KBV	0.22	
C125	ECUV1H100DCV	10P	S
C134	ECUV1H103KBV	0.01	
C135	ECUV1H103KBV	0.01	
C136	ECUV1H020CCV	2P	
C401	ECUV1E104ZFV	0.1	S
C402	ECUV1C224KBV	0.22	
		(OTHERS)	
RY1	DCR000105H7	RELAY	
SW1	DETP1200017	SWITCH	
VC1	CR01020RRT8	TRIMMER CAPACITOR	

28.2. Handset

28.2.1. CABINET AND ELECTRICAL PARTS

Ref. No.	Part No.	Part Name & Description	Remarks
101	PQJT10182Z	CHERGE TERMINAL	
102	PQGT16254Z	NAME PLATE (for KX-TC2000NZB)	
102	PQGT16258Z	NAME PLATE (for KX-TC2000NZF)	

Ref. No.	Part No.	Part Name & Description	Remarks
102	PQGT16256Z	NAME PLATE (for KX-TC2000NZW)	
103	PQKF10535Z1	REAR CABINET (for KX-TC2000NZB)	
103	PQKF10535Z2	REAR CABINET (for KX-TC2000NZF)	
103	PQKF10535Z5	REAR CABINET (for KX-TC2000NZW)	
104	PQKK10124Z1	BATTERY COVER (for KX-TC2000NZB)	
104	PQKK10124Z2	BATTERY COVER (for KX-TC2000NZF)	
104	PQKK10124Z5	BATTERY COVER (for KX-TC2000NZW)	
105	PQKM10510T1	FRONT CABINET (for KX-TC2000NZB)	
105	PQKM10510T2	FRONT CABINET (for KX-TC2000NZF)	
105	PQKM10510T5	FRONT CABINET (for KX-TC2000NZW)	
106	PQSA10130Z	ANTENNA (for KX-TC2000NZB/F)	
106	PQSA10130Y	ANTENNA (for KX-TC2000NZW)	
107	PQSX10191Z	KEYBOARD SWITCH (for KX-TC2000NZB/F)	
107	PQSX10191V	KEYBOARD SWITCH (for KX-TC2000NZW)	
108	PQXA36ASVC	BATTERY	
109	FH1T1200011	CUSHION, URETHANE FORM	
110	CG2P1200021	SPEAKER	
111	FE4T1200019	SPEAKER NET	
112	FH2T1200012	BUZZER SHEET	
113	PQHR10896Z	LIGHT PIPE	

28.2.2. MAIN P.C.BOARD PARTS

Ref. No.	Part No.	Part Name & Description	Remarks
PCB100	PQWPC2000ALR	MAIN P.C.BOARD (RTL)	
		(ICS)	
IC1	SA133122409	IC	
IC2	SA138780A05	IC	
		(TRANSISTORS)	
Q1	BB230024104	TRANSISTOR(SI)	
Q2	SB1I0390408	TRANSISTOR(SI)	
Q4	SB0I0390601	TRANSISTOR(SI)	
Q5	SB1I0390408	TRANSISTOR(SI)	
Q6	SB1I0390408	TRANSISTOR(SI)	
Q7	SB0I0390601	TRANSISTOR(SI)	
Q8	SB1I0390408	TRANSISTOR(SI)	
Q9	SB1I0390408	TRANSISTOR(SI)	
Q11	SB1I0390408	TRANSISTOR(SI)	
Q12	SB1I0390408	TRANSISTOR(SI)	
Q200	SB1D0390401	TRANSISTOR(SI)	
		(DIODES)	
D1	SC1GM414809	DIODE(SI)	
D3	SC1GM414809	DIODE(SI)	
DV1	BC6K0025101	DIODE(SI)	
ZD1	BC4579C1005	DIODE(SI)	
ZD3	SC455C5V601	DIODE(SI)	
		(LEDS)	
LED1	SC5E0192115	LED	
LED2	SC5E0192115	LED	
LED3	SC5E0192115	LED	
LED4	SC5E0192115	LED	
LED5	SC5E0192115	LED	
LED6	SC5E0192123	LED	
		(COILS)	
L1	PQLQZKR68J	COIL	
L2	PQLQZM120J	COIL	
L3	PQLQZM120J	COIL	
L4	PQLQZK120J	COIL	
L5	PQLQZK120J	COIL	
L6	PQLQZK1R8J	COIL	
L7	SH590121N75	COIL	
L200	PQLQZM1R2J	COIL	
DPX1	BDFL0083012	COIL	

Ref. No.	Part No.	Part Name & Description	Remarks
		(CERAMIC FILTERS)	
CF1	BDFA107MA07	CERAMIC FILTER	
CF2	BDFJ0455E00	CERAMIC FILTER	
		(TRANSFORMERS)	
T1	CLIP1200053	TRANSFORMER	
T3	CLIP1200126	TRANSFORMER	
T5	CLIP1200151	TRANSFORMER	
T6	CLIP1200134	TRANSFORMER	
		(CRYSTAL OSCILLATORS)	
X1	BD5H1024501	CRYSTAL OSCILLATOR	
X2	BD8Z3276800	CRYSTAL OSCILLATOR	
X3	BD5H0399209	CRYSTAL OSCILLATOR	
		(RESISTORS)	
R1	ERJ3GEYJ331	330	
R2	ERJ3GEYJ153	15K	
R3	ERJ3GEYJ682	6.8K	
R5	ERJ3GEYJ103	10K	
R6	ERJ3GEYJ103	10K	
R8	ERJ3GEYJ224	220K	
R9	ERJ3GEYJ823	82K	
R10	ERJ3GEYJ331	330	
R11	ERJ3GEYJ562	5.6K	
R12	ERJ3GEYJ224	220K	
R13	ERJ3GEYJ123	12K	
R14	ERJ3GEYJ153	15K	
R16	ERJ3GEYJ103	10K	
R17	ERJ3GEYJ103	10K	
R18	ERJ3GEYJ103	10K	
R19	ERJ3GEYJ472	4.7K	
R21	ERJ3GEYJ683	68K	
R23	ERJ3GEYJ683	68K	
R24	ERJ3GEYJ472	4.7K	
R25	ERJ3GEYJ683	68K	
R26	ERJ3GEYJ103	10K	
R28	ERJ3GEYJ104	100K	
R29	ERJ3GEYJ332	3.3K	
R30	ERJ3GEY0R00	0	
R34	ERJ3GEYJ224	220K	
R35	ERJ3GEYJ473	47K	
R36	ERJ3GEYJ202	2K	
R37	ERJ3GEYJ102	1K	
R38	ERJ3GEY0R00	0	
R39	ERJ3GEYJ224	220K	
R40	ERJ3GEYJ101	100	
R41	ERJ3GEYJ563	56K	
R42	ERJ3GEYJ223	22K	
R43	ERJ3GEYJ104	100K	
R44	ERJ3GEYJ393	39K	
R45	ERJ3GEYJ104	100K	
R46	ERJ3GEYJ434	430K	
R47	ERJ3GEYJ222	2.2K	
R48	ERJ3GEYJ223	22K	
R49	ERJ3GEYJ473	47K	
R50	ERJ3GEYJ822	8.2K	
R51	ERJ3GEYJ272	2.7K	
R52	ERJ3GEYJ222	2.2K	
R53	ERJ3GEYJ820	82	
R54	ERJ3GEYJ104	100K	
R55	ERJ3GEYJ221	220	
R56	ERJ3GEYJ122	1.2K	
R57	ERJ3GEYJ102	1K	
R58	ERJ3GEYJ102	1K	
R59	ERJ3GEYJ222	2.2K	
R60	ERJ3GEYJ222	2.2K	
R61	ERJ3GEYJ331	330	
R62	ERJ3GEYJ222	2.2K	
R63	ERJ3GEYJ103	10K	
R64	ERJ3GEYJ103	10K	
R65	ERJ3GEYJ331	330	
R66	ERJ3GEYJ222	2.2K	
R67	ERJ3GEYJ222	2.2K	
R68	ERJ3GEYJ103	10K	
R69	ERJ3GEYJ222	2.2K	

Ref. No.	Part No.	Part Name & Description	Remarks
R70	ERJ3GEYJ222	2.2K	
R73	ERJ3GEYJ105	1M	
R74	ERJ3GEYJ104	100K	
R75	ERJ3GEYJ104	100K	
R76	ERJ3GEYJ104	100K	
R77	ERJ3GEYJ103	10K	
R78	ERJ3GEYJ104	100K	
R79	ERJ3GEYJ105	1M	
R80	ERJ3GEYJ105	1M	
R82	ERJ3GEY0R00	0	
R83	ERJ3GEY0R00	0	
R84	ERJ3GEYJ105	1M	
R85	ERJ3GEYJ102	1K	
R86	ERJ3GEYJ104	100K	
R87	ERJ3GEYJ104	100K	
R93	ERJ3GEYJ103	10K	
R94	ERJ3GEYJ334	330K	
R95	ERJ3GEYJ393	39K	
R96	ERJ3GEY0R00	0	
R97	ERJ3GEYJ154	150K	
R98	ERJ3GEYJ475	4.7M	
R99	ERJ3GEYJ472	4.7K	
R101	ERJ3GEY0R00	0	
R102	ECUV1H683ZFV	0.068	
R103	ERJ3GEYJ394	390K	
R105	ERJ3GEYJ103	10K	
R106	ERJ3GEYJ820	82	
R107	ERJ3GEYJ222	2.2K	
R108	ERJ3GEYJ102	1K	
R109	ERJ3GEYJ102	1K	
R110	ERJ3GEYJ102	1K	
R111	ERJ3GEYJ102	1K	
R112	ERJ3GEYJ102	1K	
R200	ERJ3GEYJ473	47K	
R201	ERJ3GEYJ330	33	
		(CAPACITORS)	
C1	ECEA1AKA470	47	
C2	ECUV1E104ZFV	0.1	S
C4	ECUV1H270JCV	27P	
C5	ECUV1E104ZFV	0.1	S
C6	ECUV1H102KBV	0.001	
C7	ECUV1E104ZFV	0.1	S
C8	ECUV1H473MDV	0.047	S
C9	ECUV1H103KBV	0.01	
C12	ECEA1HKA2R2	2.2	
C13	ECUV1H270JCV	27P	
C14	ECUV1H103KBV	0.01	
C15	ECEA1CKA100	10	
C16	ECUV1H473MDV	0.047	S
C17	ECUV1H102KBV	0.001	
C18	ECEA1HKA2R2	2.2	
C21	ECUV1H223KBV	0.022	S
C22	ECUV1H103KBV	0.01	
C23	ECUV1H102KBV	0.001	
C24	ECUV1H220JCV	22P	
C26	ECUV1H103KBV	0.01	
C27	ECUV1E104ZFV	0.1	S
C28	ECUV1H682KBV	0.0068	
C29	ECEA1HKA2R2	2.2	
C30	ECUV1E104ZFV	0.1	S
C31	ECUV1H103KBV	0.01	
C32	ECUV1E104ZFV	0.1	S
C33	ECUV1E104ZFV	0.1	S
C34	ECUV1H101JCV	100P	
C35	ECUV1H681JCV	680P	S
C36	ECUV1H180JCV	18P	
C37	ECEA1HKS010	1	S
C38	ECUV1H101JCV	100P	
C39	ECUV1H151JCV	150P	
C40	ECUV1H103KBV	0.01	
C41	ECUV1H270JCV	27P	
C42	ECEA1AKA470	47	
C43	ECEA1HKA2R2	2.2	

Ref. No.	Part No.	Part Name & Description	Remarks
C44	ECUV1H105ZFV	1	
C45	ECUV1C683KBV	0.068	
C46	ECUV1H103KBV	0.01	
C47	ECUV1H682KBV	0.0068	
C48	ECEA1AKA470	47	
C49	ECUV1H223KBV	0.022	S
C50	ECUV1H103KBV	0.01	
C51	ECEA1CKA100	10	
C52	ECUV1H103KBV	0.01	
C53	ECUV1H223KBV	0.022	S
C54	ECUV1H220JCV	22P	
C55	ECUV1H103KBV	0.01	
C56	ECUV1H050CCV	5P	
C57	ECUV1H150JCV	15P	
C58	ECUV1H103KBV	0.01	
C59	ECUV1H390JCV	39P	
C60	ECUV1H270JCV	27P	
C61	ECUV1E104ZFV	0.1	S
C62	ECUV1H390JCV	39P	
C63	ECEA1AKA101	100	
C64	ECUV1H103KBV	0.01	
C65	ECUV1H150JCV	15P	
C66	ECUV1H150JCV	15P	
C69	ECUV1E104ZFV	0.1	S
C70	ECUV1H330JCV	33P	
C71	ECUV1H330JCV	33P	
C72	ECUV1E104ZFV	0.1	S
C73	ECUV1E104ZFV	0.1	S
C74	ECUV1H473MDV	0.047	S
C75	ECUV1H103KBV	0.01	
C76	ECUV1H471JCV	470P	S
C77	ECUV1H471JCV	470P	S
C78	ECUV1H103KBV	0.01	
C79	ECUV1H103KBV	0.01	
C80	ECUV1H103KBV	0.01	
C84	ECUV1E104ZFV	0.1	S
C85	ECUV1H105ZFV	1	
C86	ECUV1E104ZFV	0.1	S
C88	ECUV1E104ZFV	0.1	S
C200	ECUV1H390JCV	39P	
C201	ECUV1H680JCV	68P	
C202	ECUV1H121JCV	120P	
		(OTHERS)	
E101	CK15HC12G10	BUZZER	
E102	CGAP1200019	MICROPHONE	
E103	PQJT10183Z	CHARGE CONTACT	S
VC1	CR01020RRT8	TRIMMER CAPACITOR	
BATT1	DCB002X1164	CONNECTOR	

28.3. ACCESSORIES AND PACKING MATERIALS

Ref. No.	Part No.	Part Name & Description	Remarks
A1	PQJA87S	TEL CORD	
A2	PQLV16ALZ	AC ADAPTOR	⚠
A3	PQQX13660Z	INSTRUCTION BOOK	
P1	PQPP10104Z	PROTECTION COVER (for BASE UNIT)	
P2	PQPP10105Z	PROTECTION COVER (for HANDSET)	
P3	PQPK14094Z	GIFT BOX	
P4	PQPD10579Z	CUSHION, AC ADAPTOR	

29 FOR SCHEMATIC DIAGRAM

29.1.   Base Unit (SCHEMATIC DIAGRAM (Base Unit))

1. DC voltage measurements are taken with an oscilloscope or a tester with a ground.

2. The schematic diagrams and circuit board may be modified at any time with the development of new technology.

> **Important Safety Notice:**
> Components identified by ⚠ mark have special characteristics important for safety. When replacing any of these components, use only the manufacturer´s specified parts.

29.2.   Handset (SCHEMATIC DIAGRAM (Handset))

1. DC voltage measurements are taken with an oscilloscope or a tester with a ground.

2. The schematic diagrams and circuit board may be modified at any time with the development of new technology.

30 SCHEMATIC DIAGRAM (Base Unit)

30.1. Base Unit
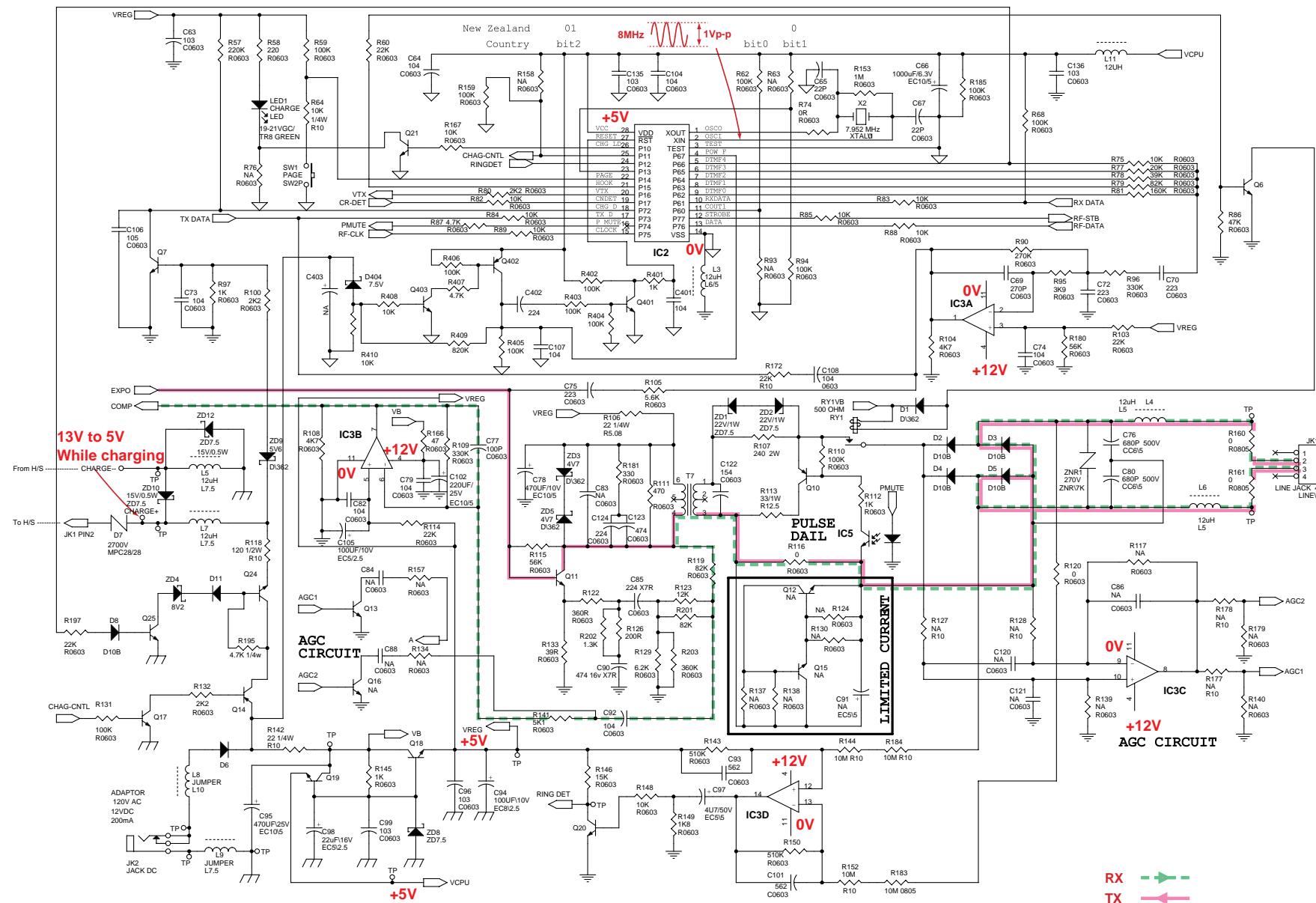
KX-TC2000NZB/NZW/NZF SCHEMATIC DIAGRAM (Base Unit)

30.2. RF Unit (Base Unit)

KX-TC2000NZB/NZW/NZF SCHEMATIC DIAGRAM (Base Unit)
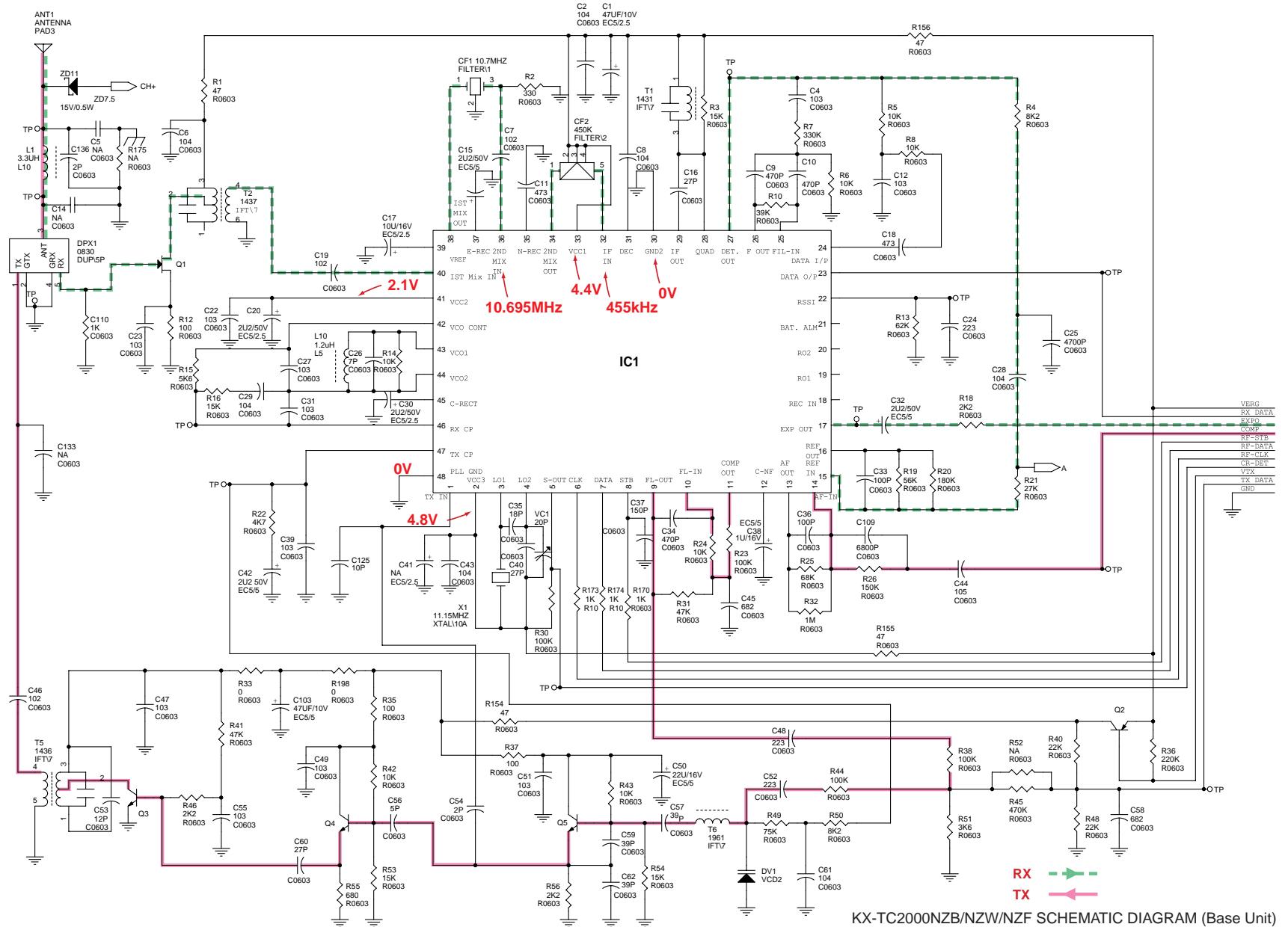
KX-TC2000NZB / KX-TC2000NZW / KX-TC2000NZF

31 SCHEMATIC DIAGRAM (Handset)

31.1. Handset
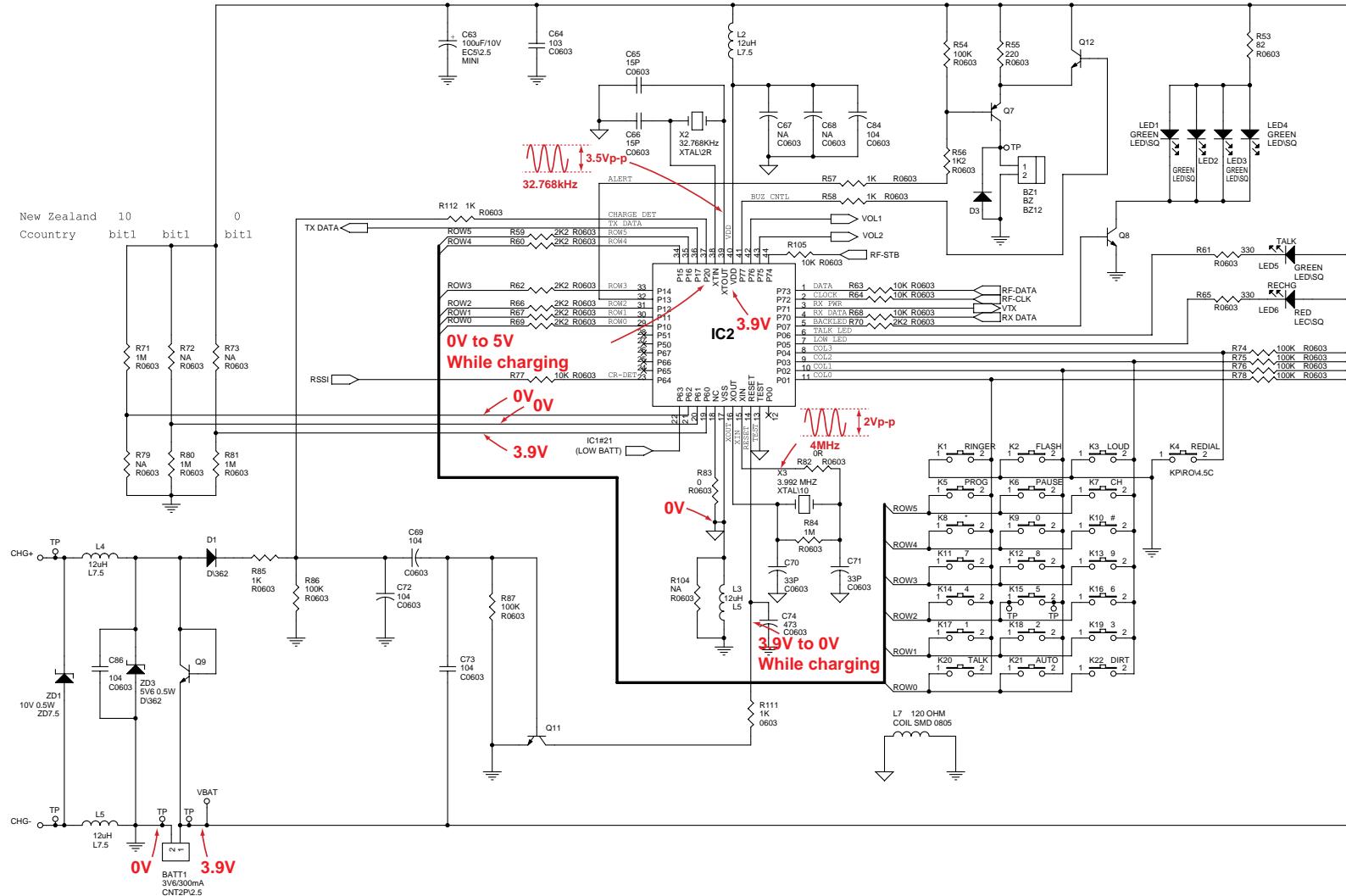
KX-TC2000NZB/NZW/NZF SCHEMATIC DIAGRAM (Handset)

31.2. RF Unit (Handset)
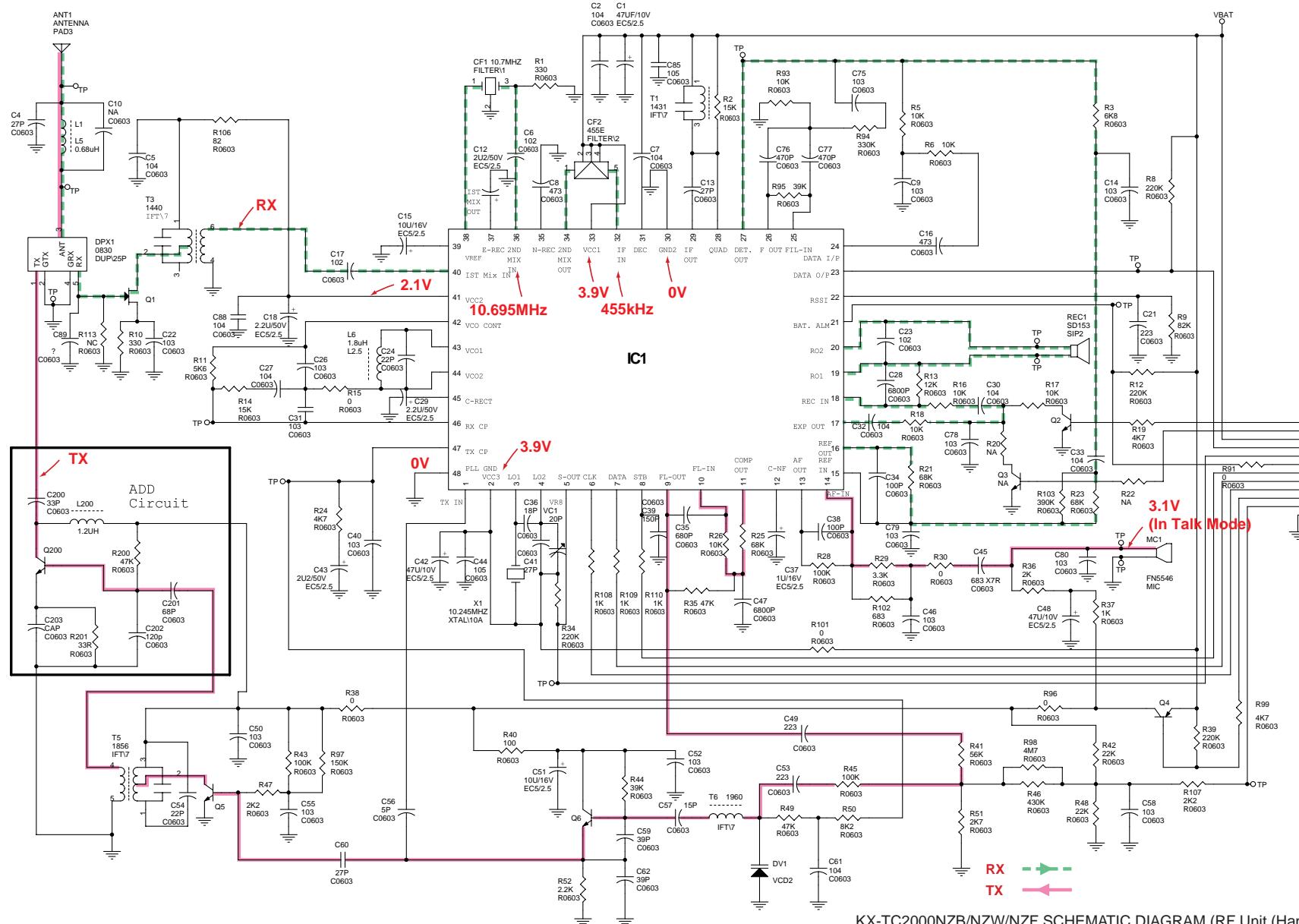
KX-TC2000NZB/NZW/NZF SCHEMATIC DIAGRAM (RF Unit (Handset))

31.3. Memo

32 CIRCUIT BOARD (Base Unit)

32.1. Component View
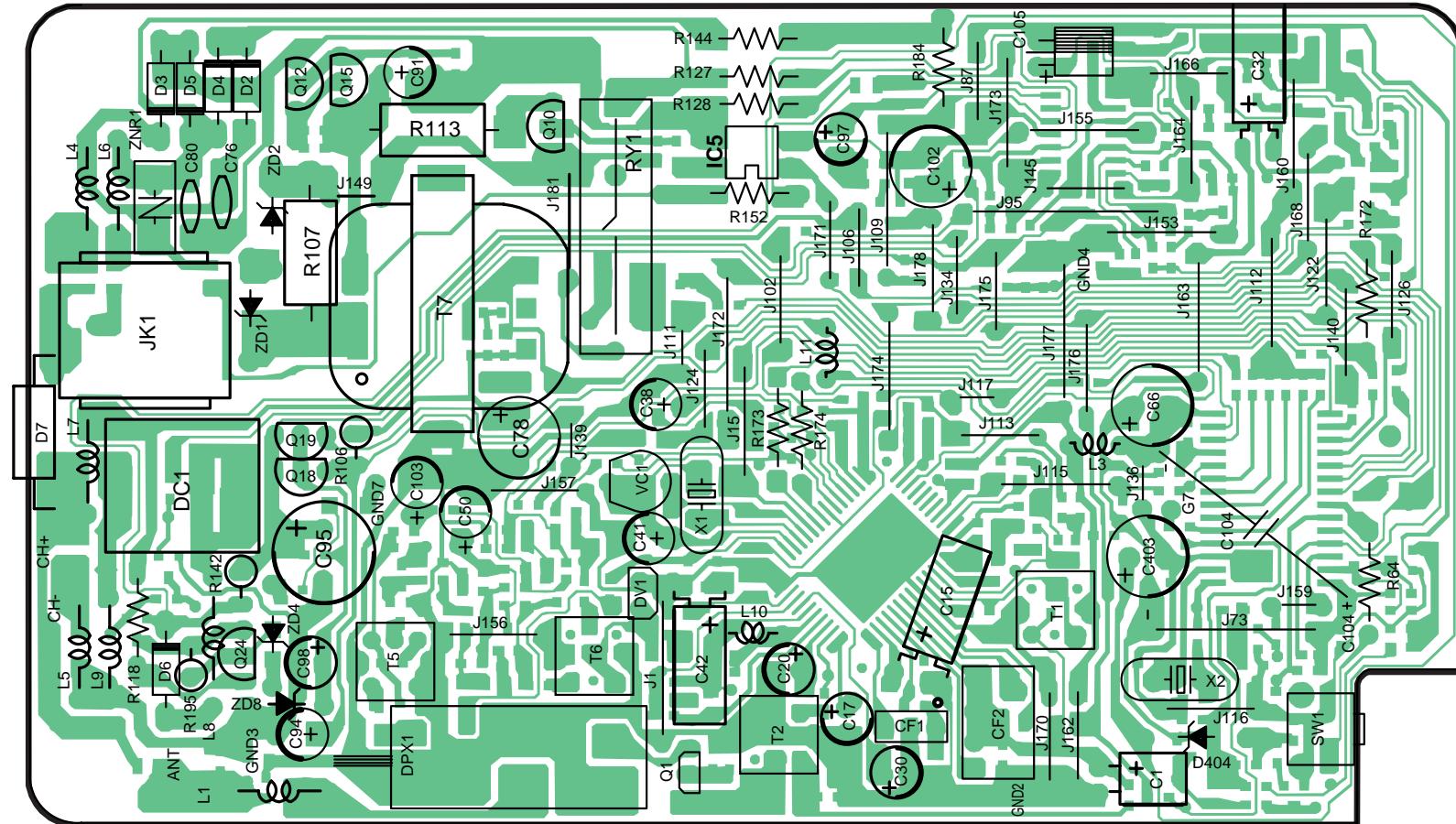
KX-TC2000NZB/NZW/NZF CIRCUIT BOARD (Component View (Base Unit))

32.2. Flow Solder Side View

KX-TC2000NZB/NZW/NZF CIRCUIT BOARD (Flow Solder Side View (Base Unit))
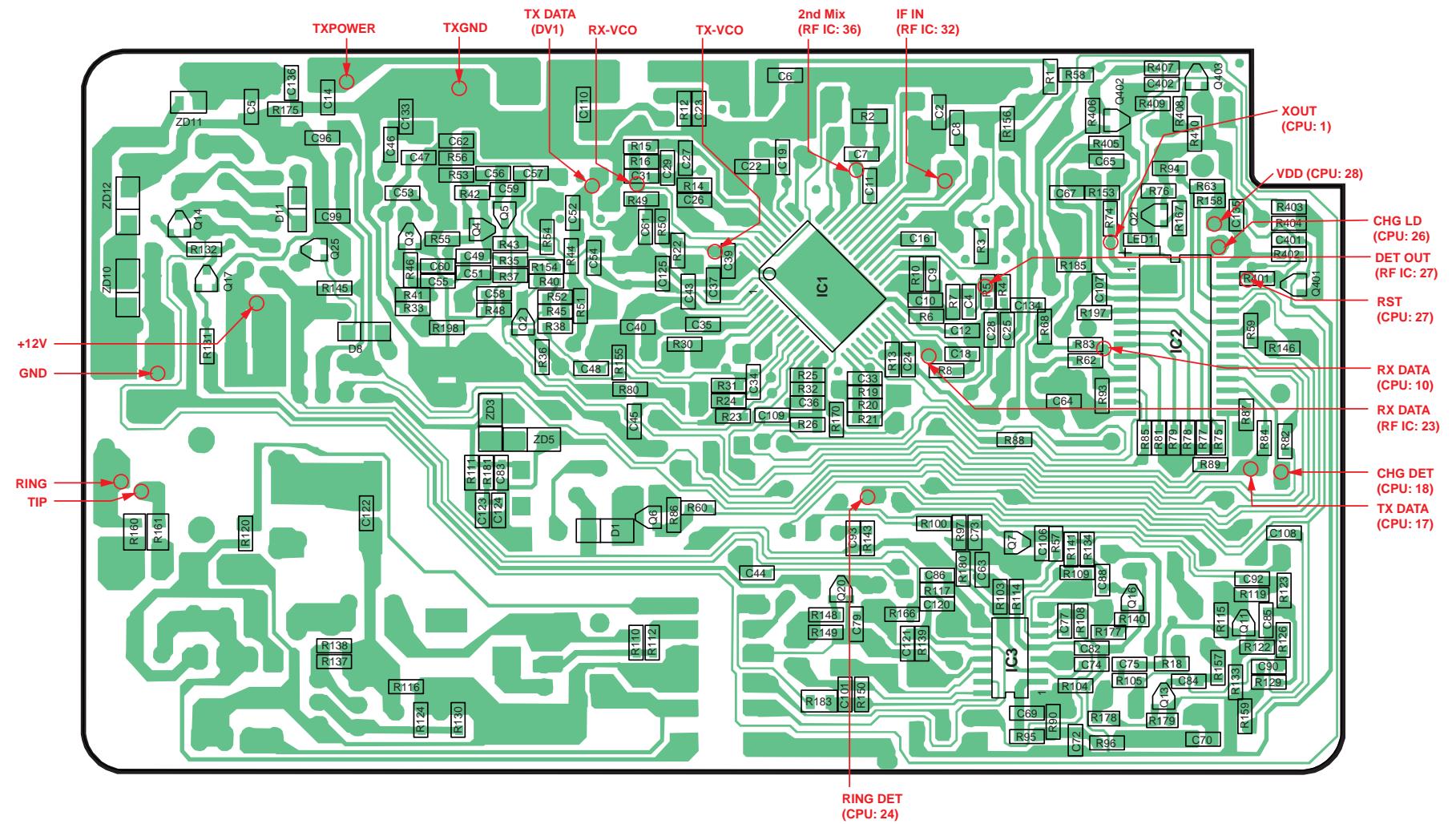
33 CIRCUIT BOARD (Handset)

33.1. Component View
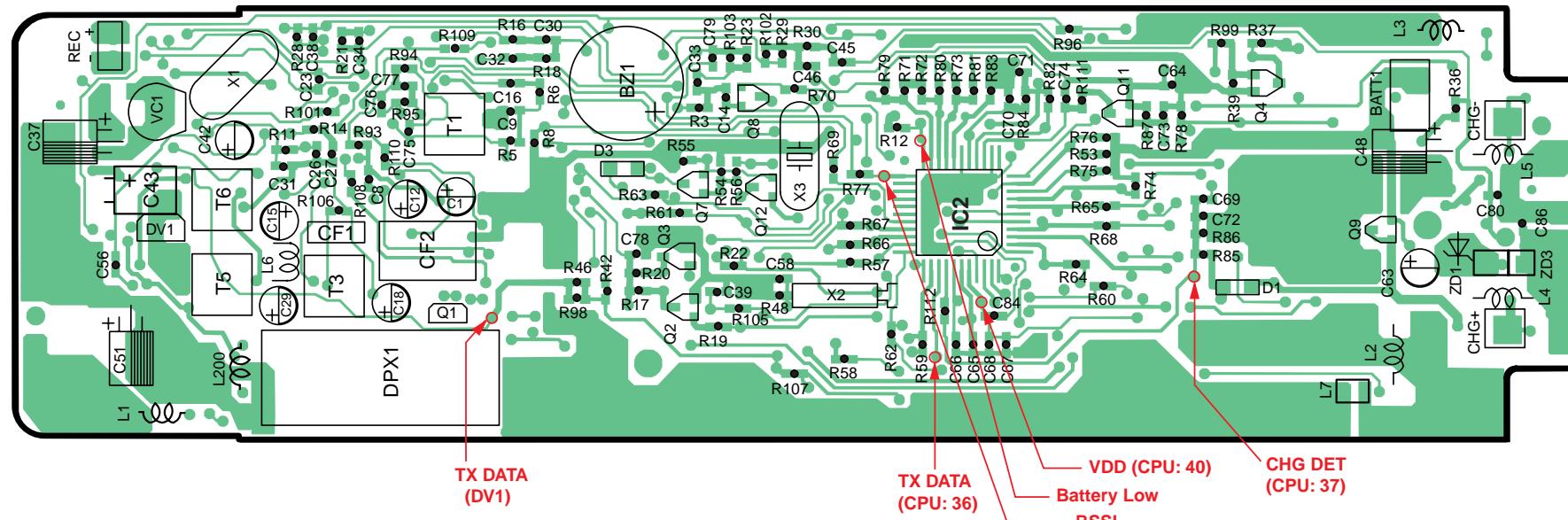
KX-TC2000NZB/NZW/NZF CIRCUIT BOARD (Component View (Handset))

33.2. Flow Solder Side View
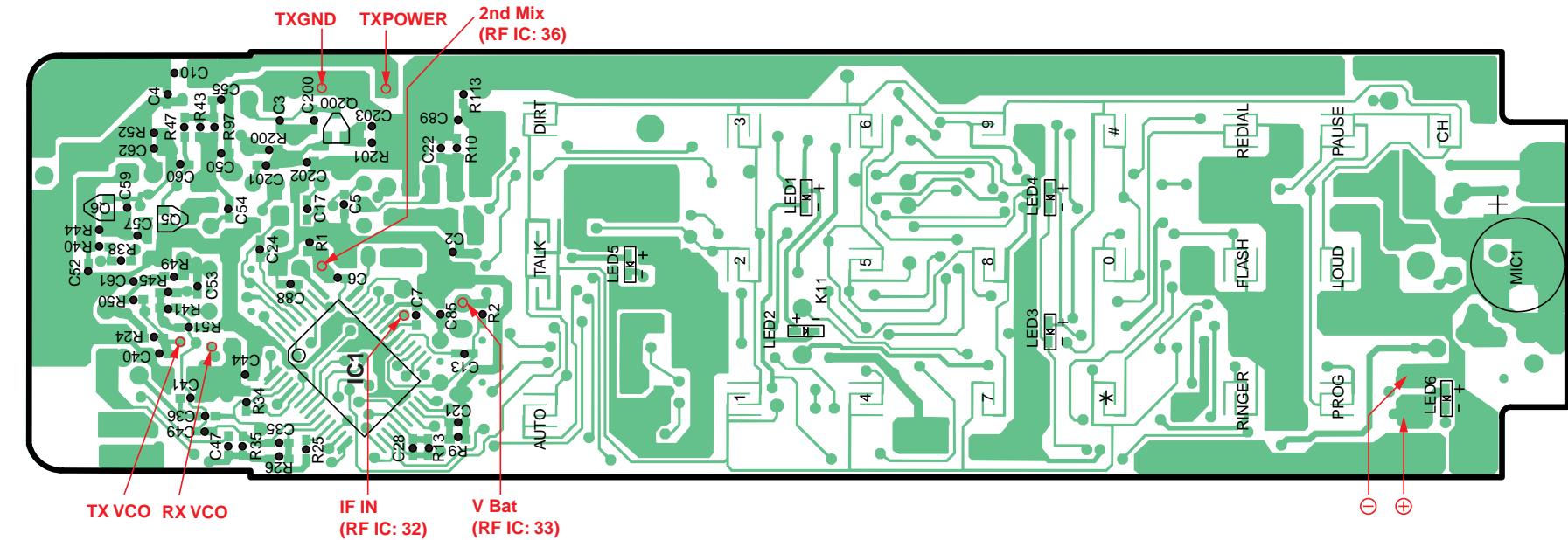
KX-TC2000NZB/NZW/NZF CIRCUIT BOARD (Flow Solder Side View (Handset))

G
KXTC2000NZB
KXTC2000NZW
KXTC2000NZF